



Electronics Systems (938II)

Lecture 3.6

Semiconductor Memories – DRAM, SDRAM, and DDR

RAM – Reminder

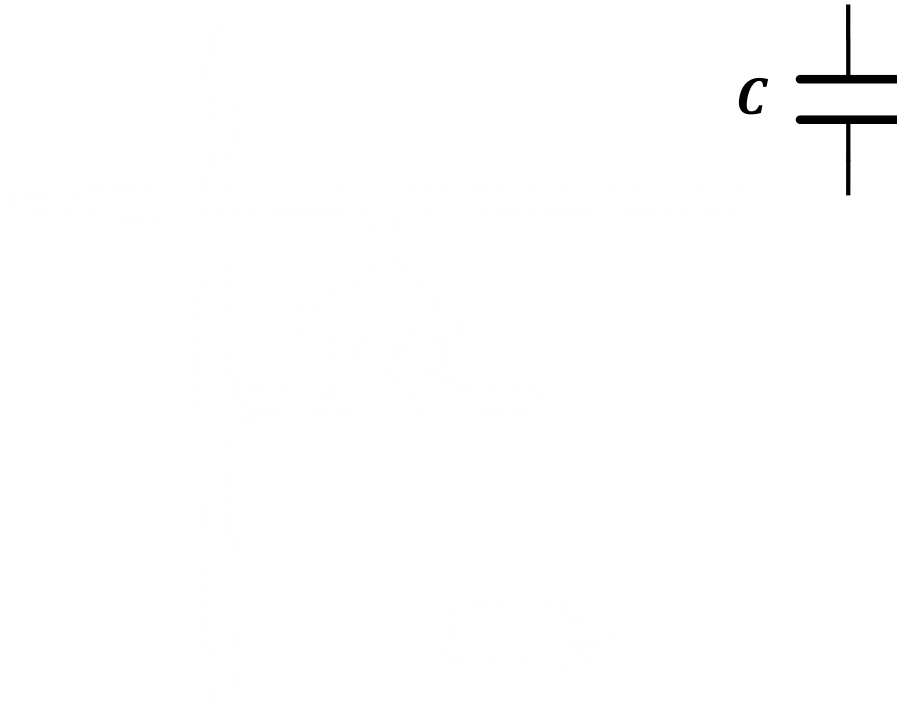
- RAM classification
 - **Static RAM (SRAM)**
 - The memory content is hold over the time, as long as the memory is powered
 - **Dynamic RAM (DRAM)**
 - Even if the memory is powered, the memory content needs to be refreshed over the time, otherwise it is lost

RAM – Reminder

- RAM classification
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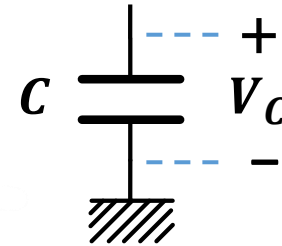
DRAM – Memory cell

- Capacitor



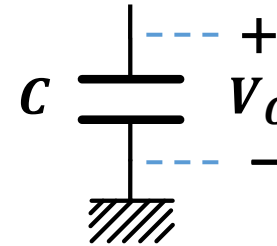
DRAM – Memory cell

- Capacitor
 - **Memory bit = Voltage on capacitor (V_c)**

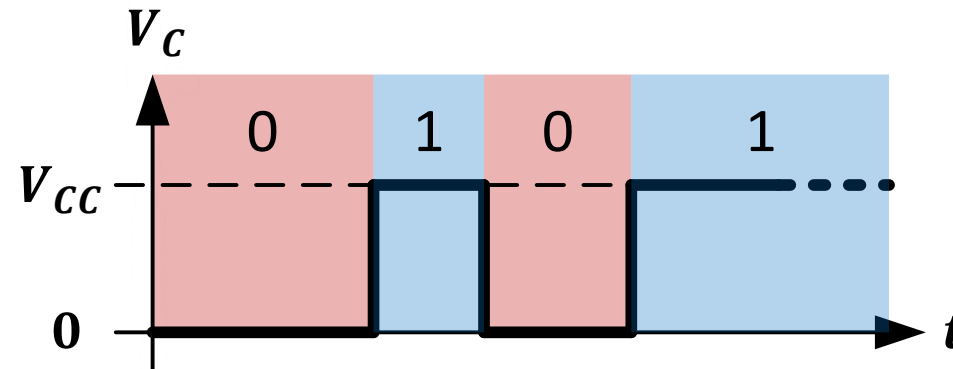


DRAM – Memory cell

- Capacitor
 - Memory bit = Voltage on capacitor (V_C)

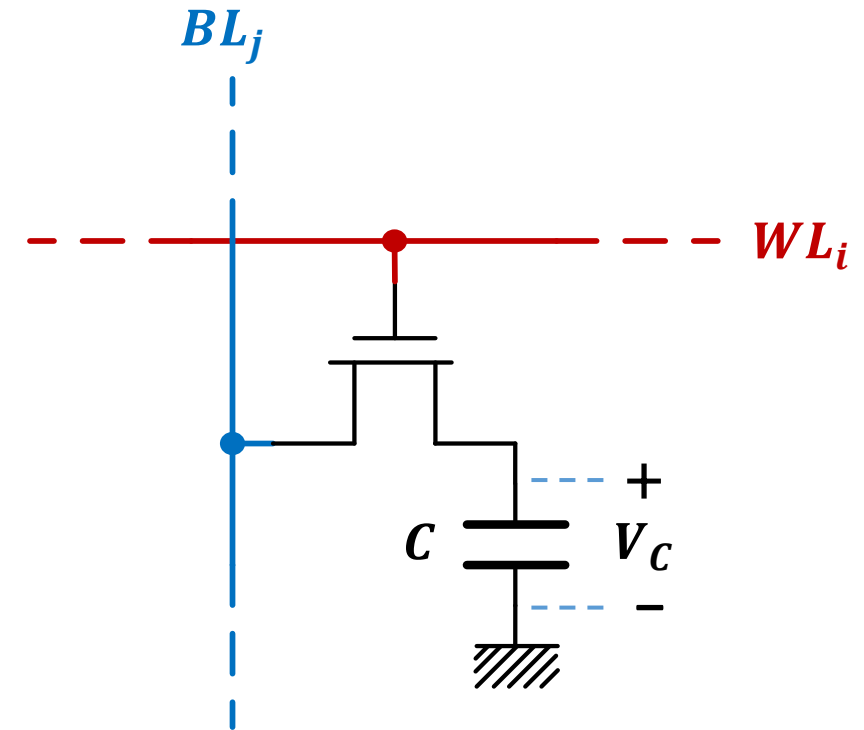


$$V_C = \begin{cases} V_{CC} & (\text{logic 1}) \\ 0 & (\text{logic 0}) \end{cases}$$



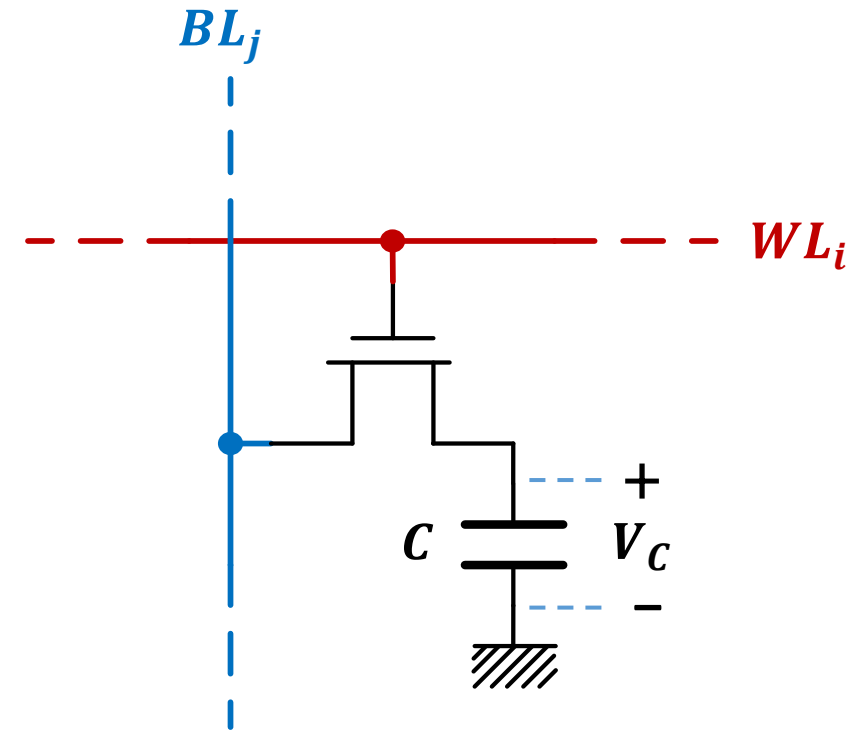
DRAM – Memory cell

- Architecture
 - Capacitor
 - 1x access transistor
 - WL_i = Word Line
 - BL_j = Bit Line



DRAM – Memory cell

- Working principle

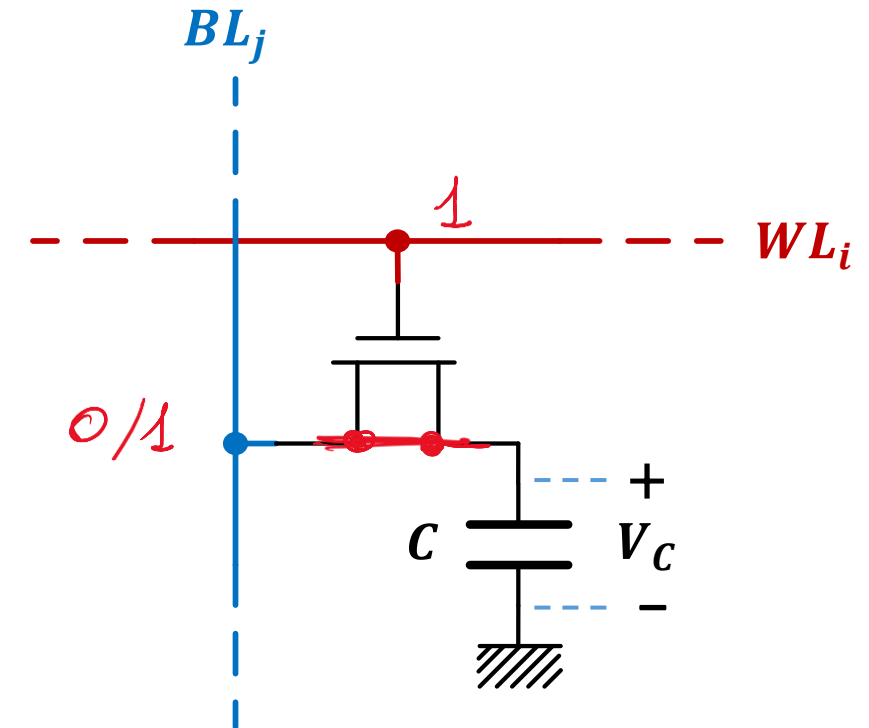


DRAM – Memory cell

- Working principle

- Write

- $WL_i = 1$
- $BL_i = D$
 - 0 V (logic 0)
 - V_{CC} (logic 1)

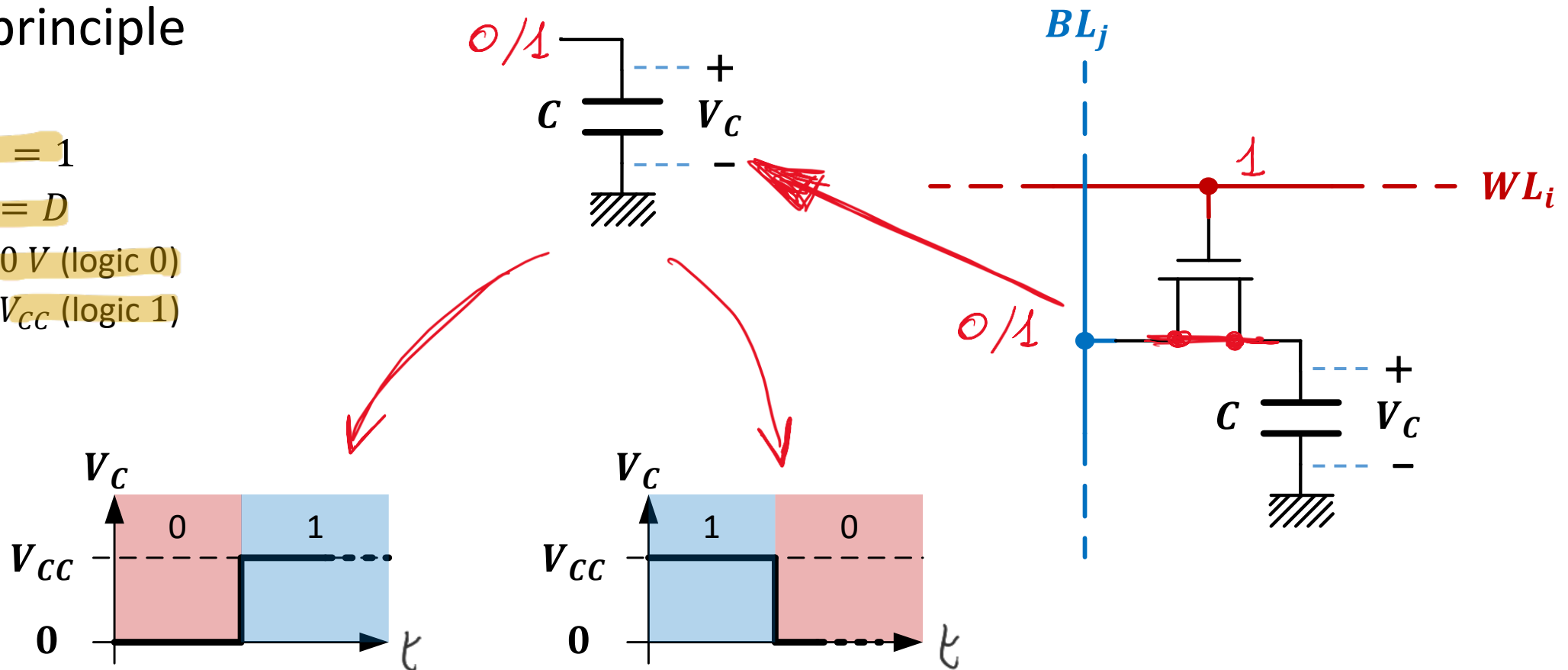


DRAM – Memory cell

- Working principle

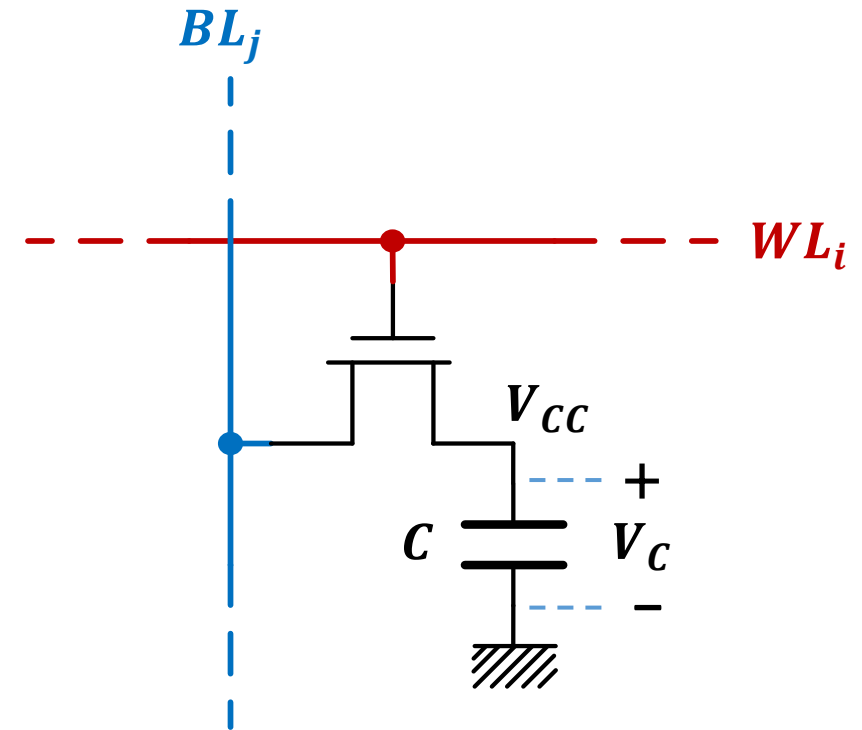
- Write

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- $BL_i = D$
 - 0 V (logic 0)
 - V_{CC} (logic 1)



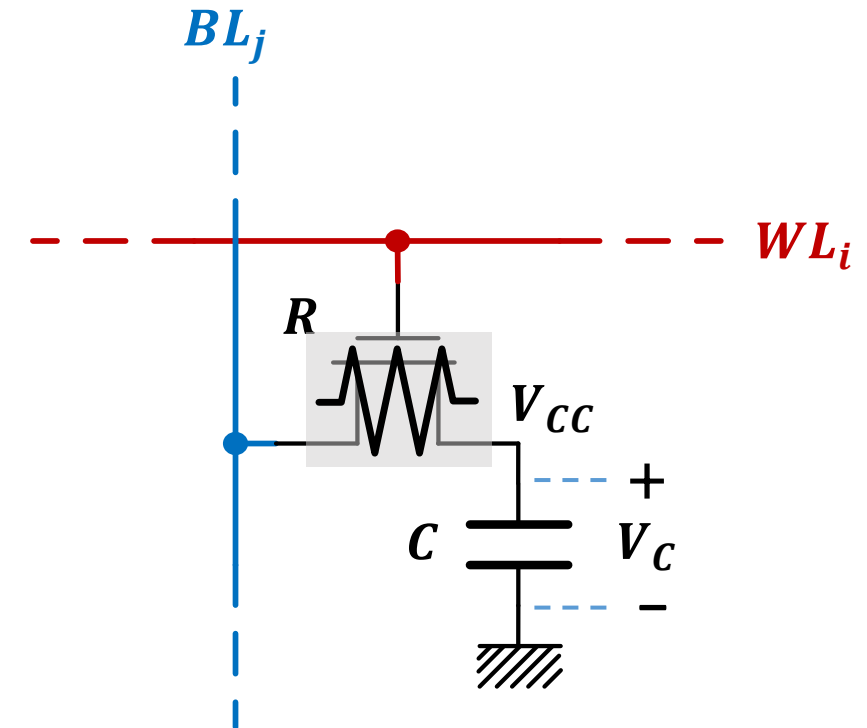
DRAM – Memory cell

- Working principle
 - **After write**
 - $WL_i = 0$
 - Assume 1 (V_{CC}) written in memory cell / on capacitor



DRAM – Memory cell

- Working principle
 - After write
 - $WL_i = 0$
 - Assume 1 (V_{CC}) written in memory cell / on capacitor
 - **Access transistor \approx resistor (R)**
 - High impedance when $WL_i = 0$ (transistor OFF)



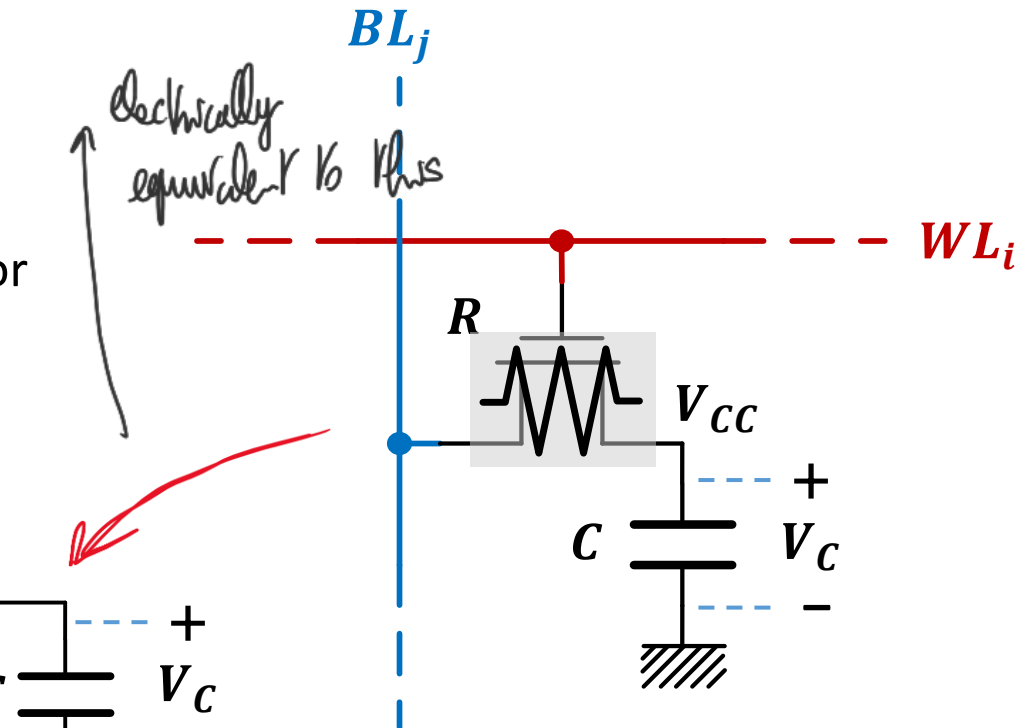
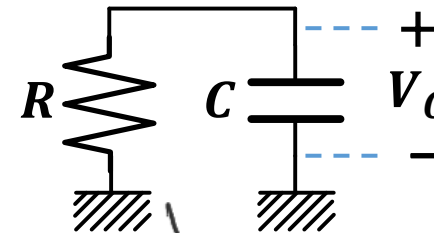
DRAM – Memory cell

- Working principle

- After write

- $WL_i = 0$
- Assume 1 (V_{CC}) written in memory cell / on capacitor
- Access transistor \approx resistor (R)
 - High impedance when $WL_i = 0$ (transistor OFF)

So we can assume
R is very high.



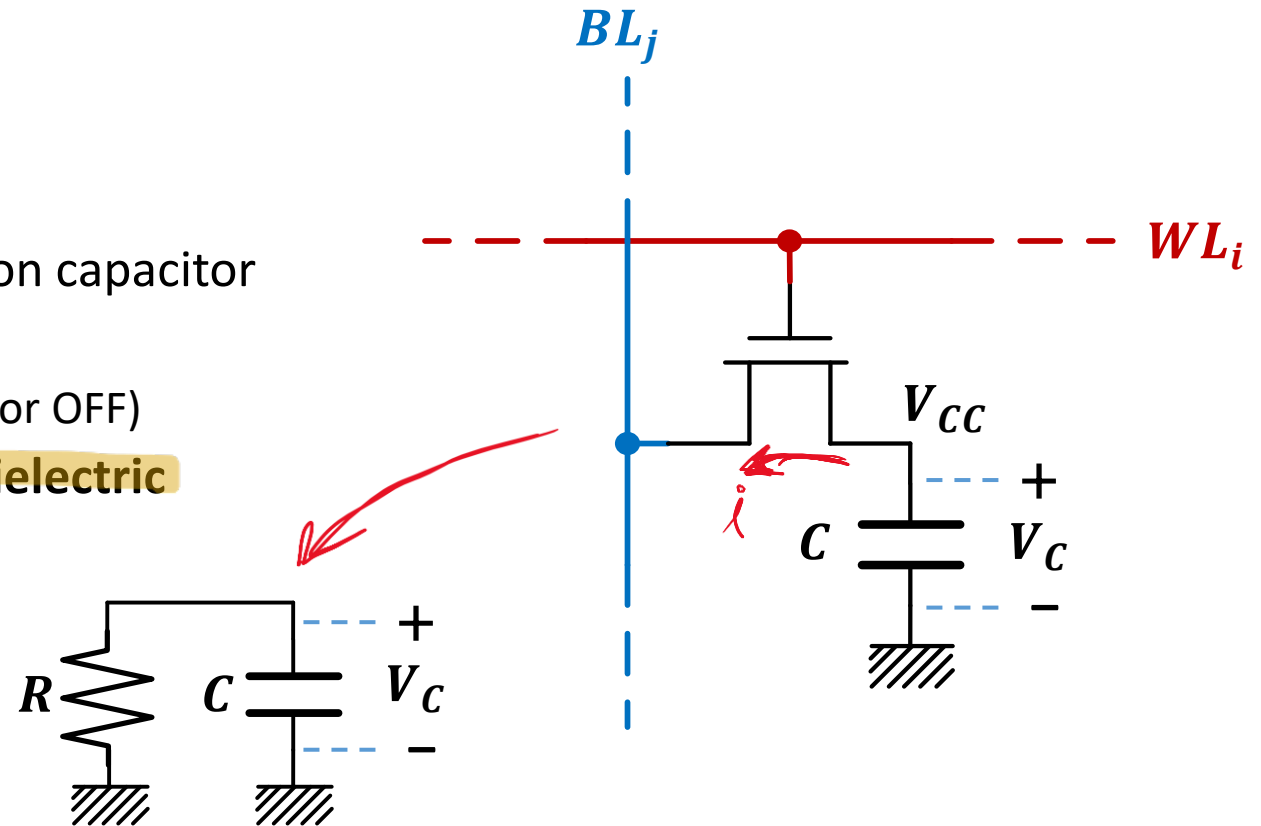
you assume everything connected between
capacitor and ground a very
big resistance

DRAM – Memory cell

- Working principle

- After write

- $WL_i = 0$
 - Assume 1 (V_{CC}) written in memory cell / on capacitor
 - Access transistor \approx resistor (R)
 - High impedance when $WL_i = 0$ (transistor OFF)
 - Leakage (current, i) through capacitor dielectric
 - Not ideal!

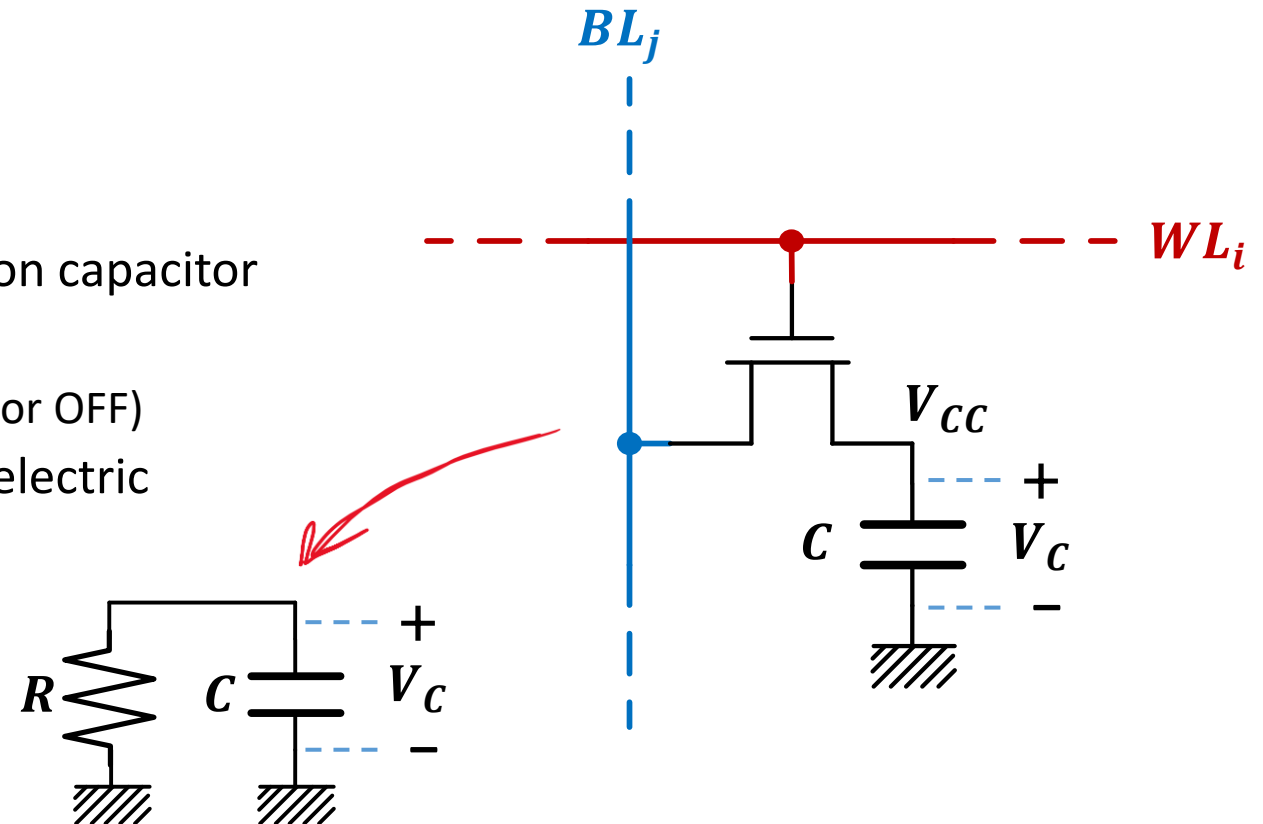


DRAM – Memory cell

- Working principle

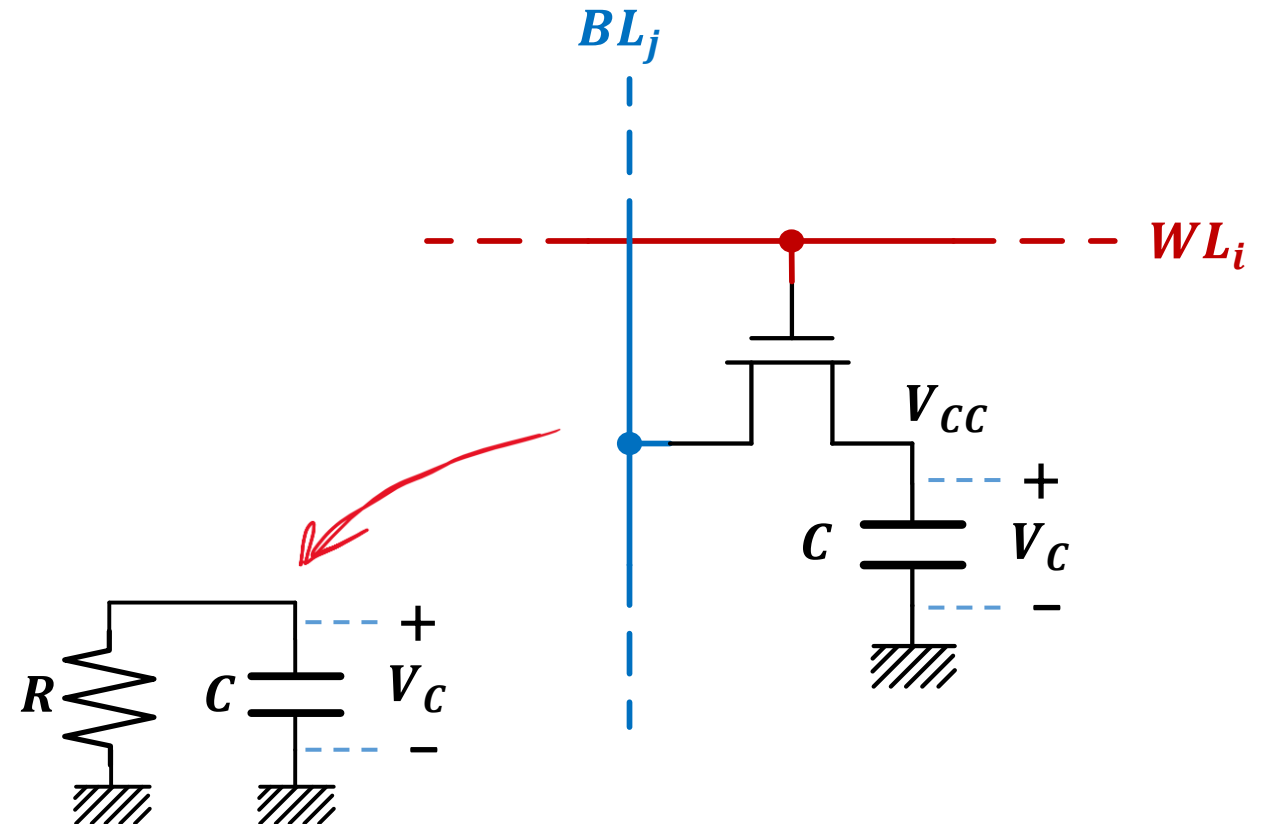
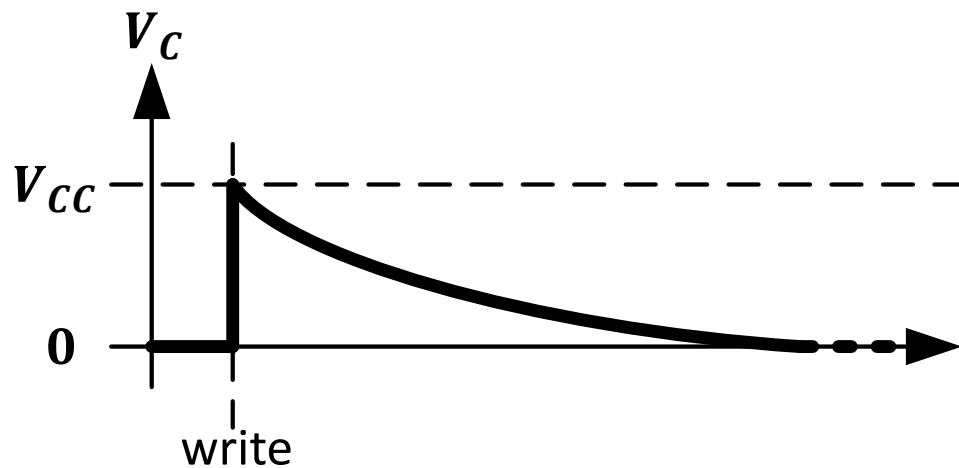
- After write

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 - Not ideal!
 - **C discharges!!!**



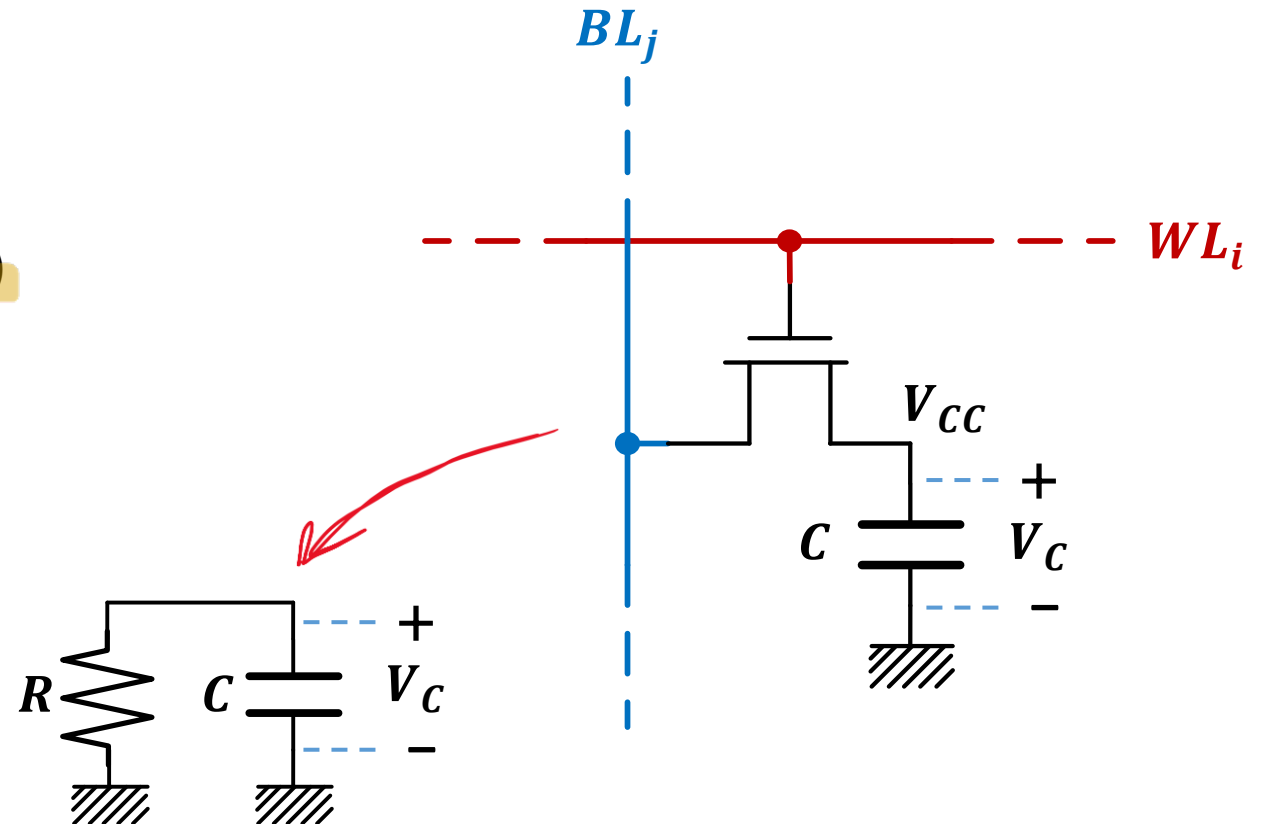
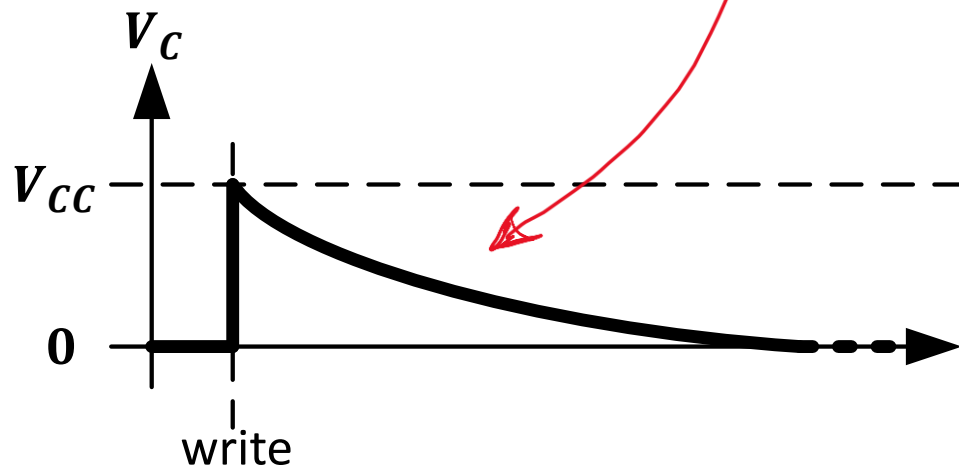
DRAM – Memory cell

- Working principle
 - After write
 - C discharges!!!



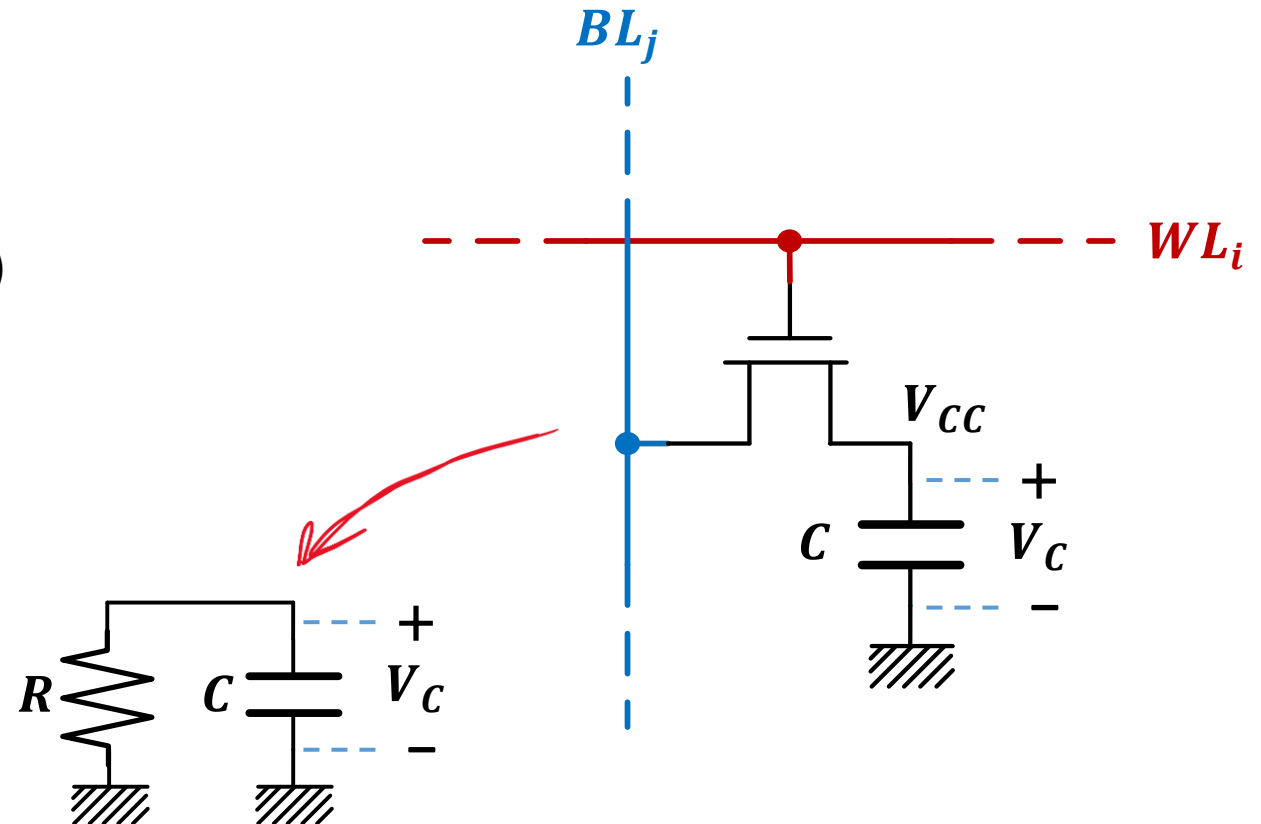
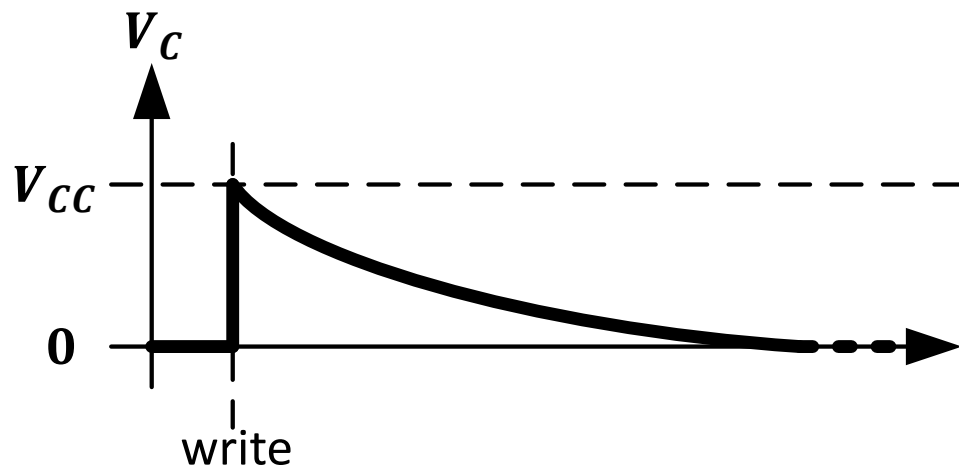
DRAM – Memory cell

- Working principle
 - After write
 - C discharges!!!
 - Proportional to $R \cdot C = \tau$ (time constant)



DRAM – Memory cell

- Working principle
 - After write
 - C discharges!!!
 - Proportional to $R \cdot C = \tau$ (time constant)
 - $\tau = 10 \div 100 \text{ ms}$



DRAM – Memory cell

- Working principle

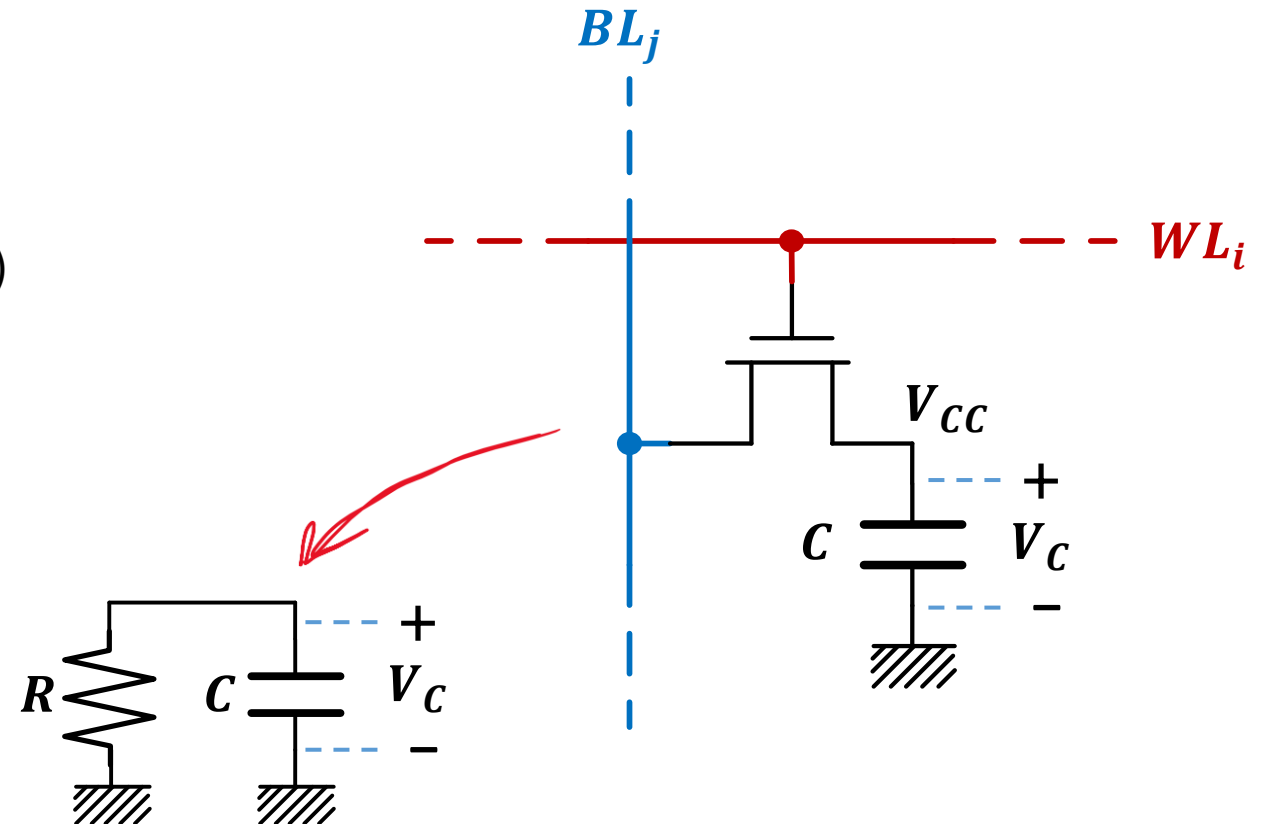
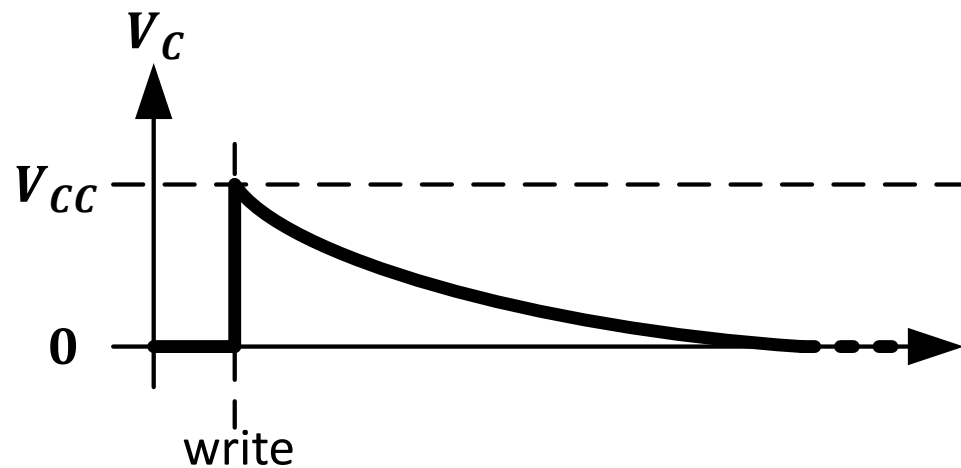
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- Need of refresh



DRAM – Memory cell

- Working principle

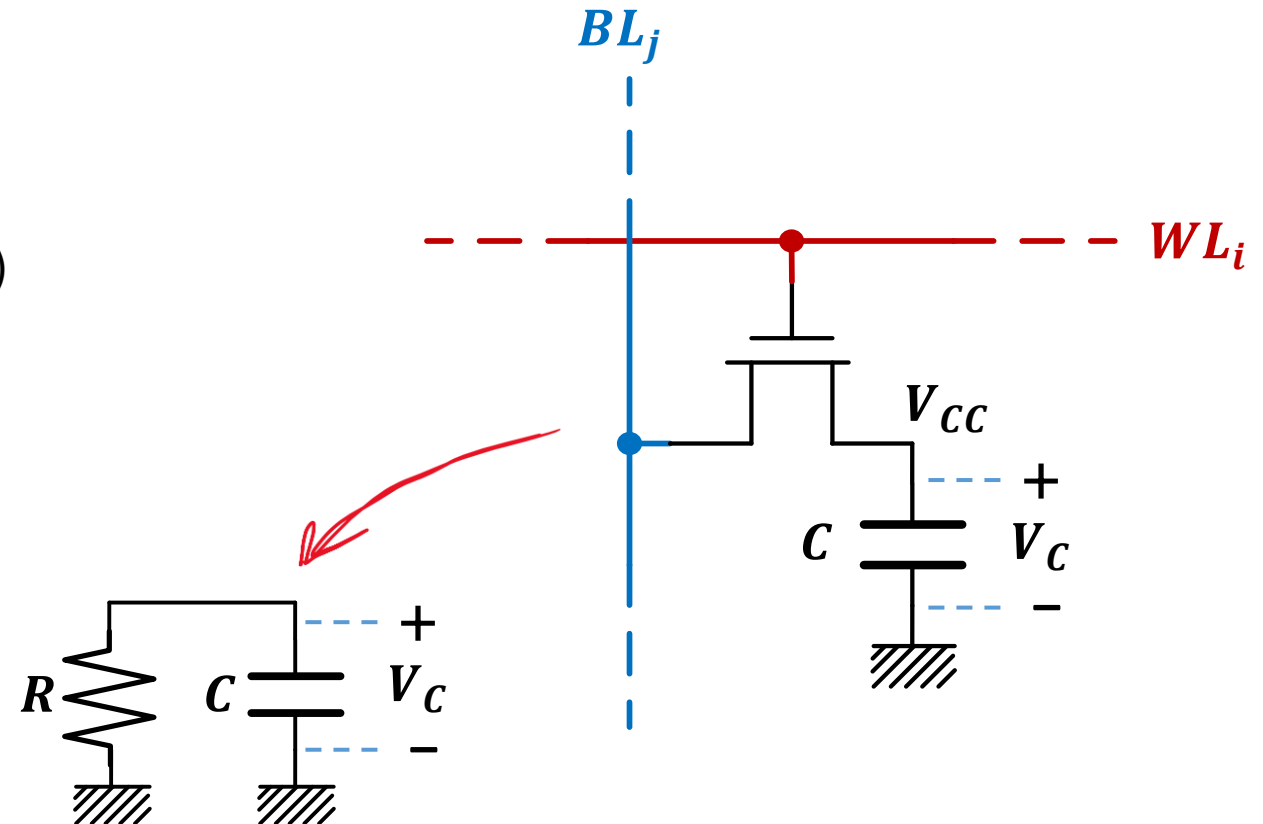
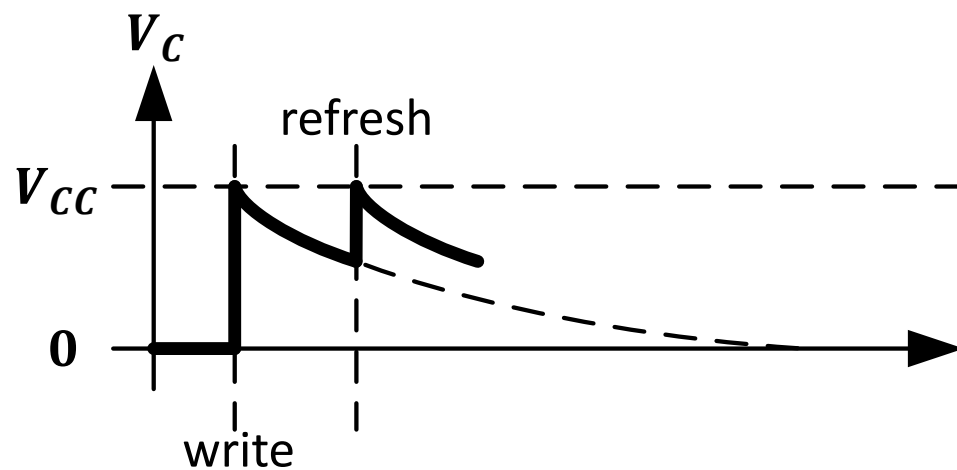
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DRAM – Memory cell

- Working principle

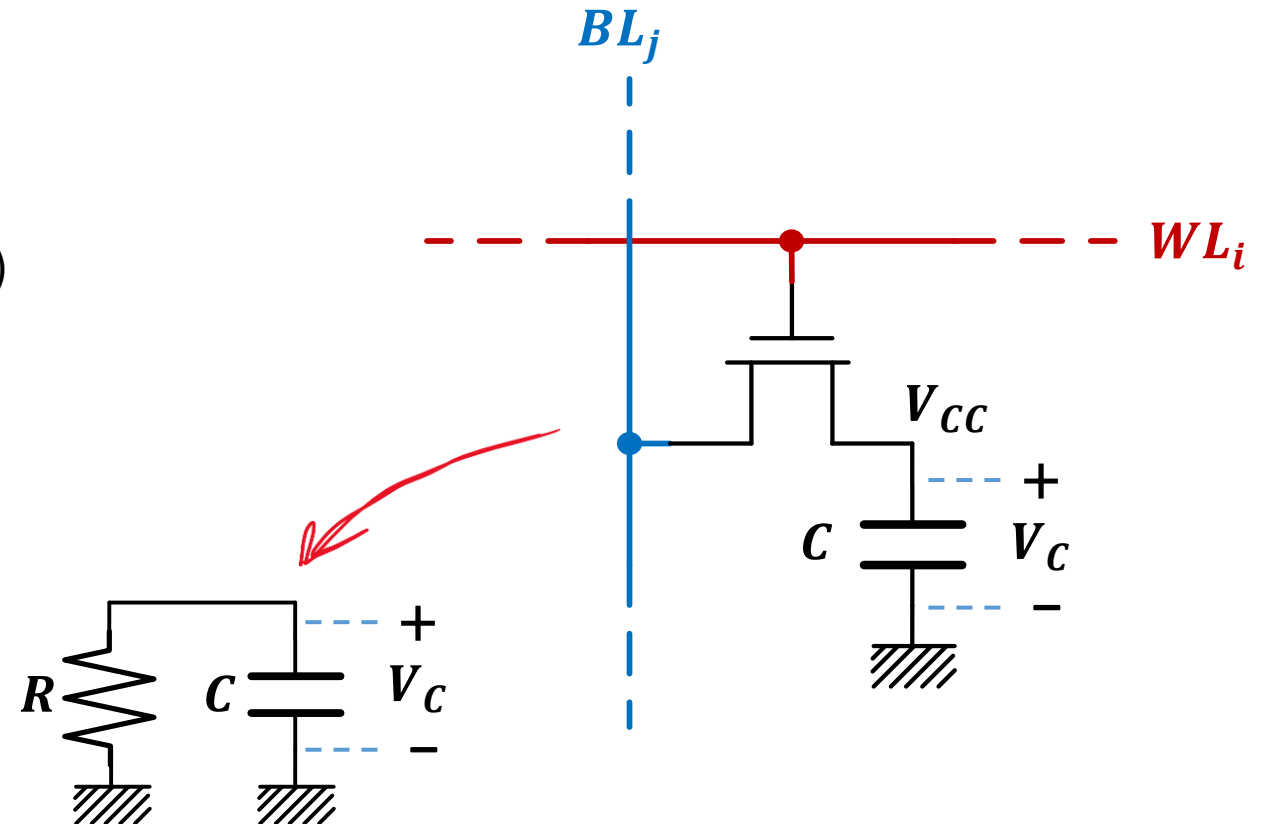
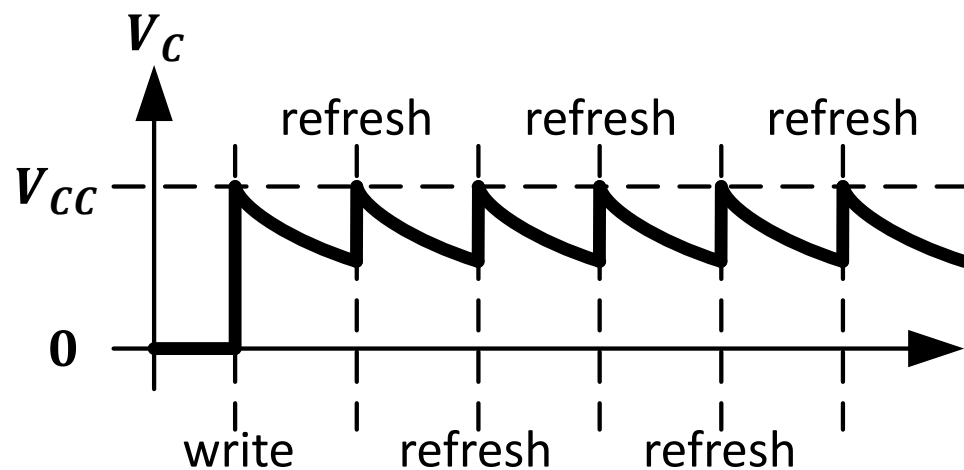
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- Proportional to $R \cdot C = \tau$ (time constant)

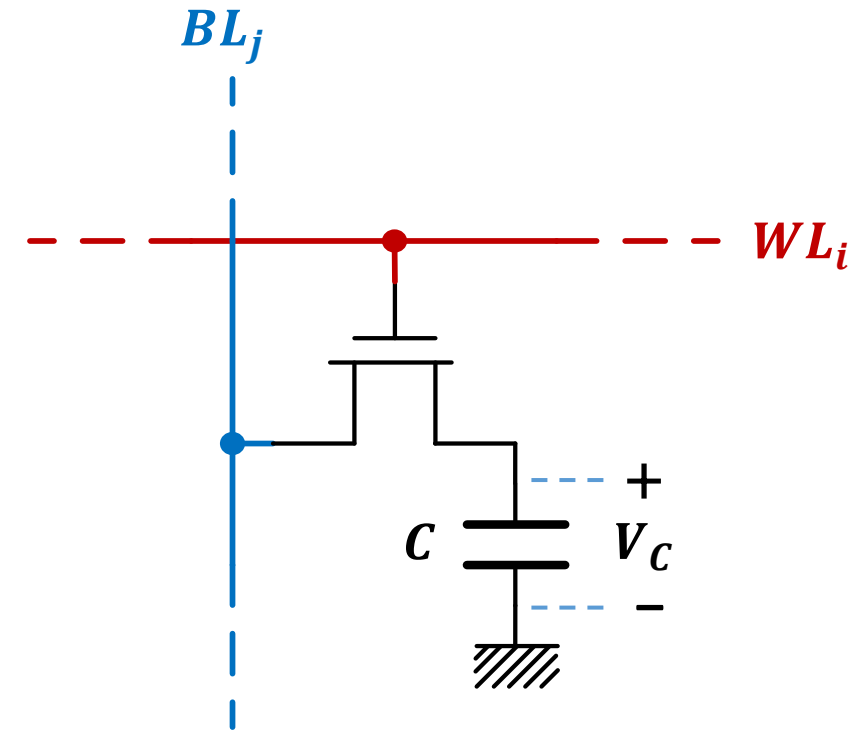
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DRAM – Memory cell

- Working principle
 - **Read**



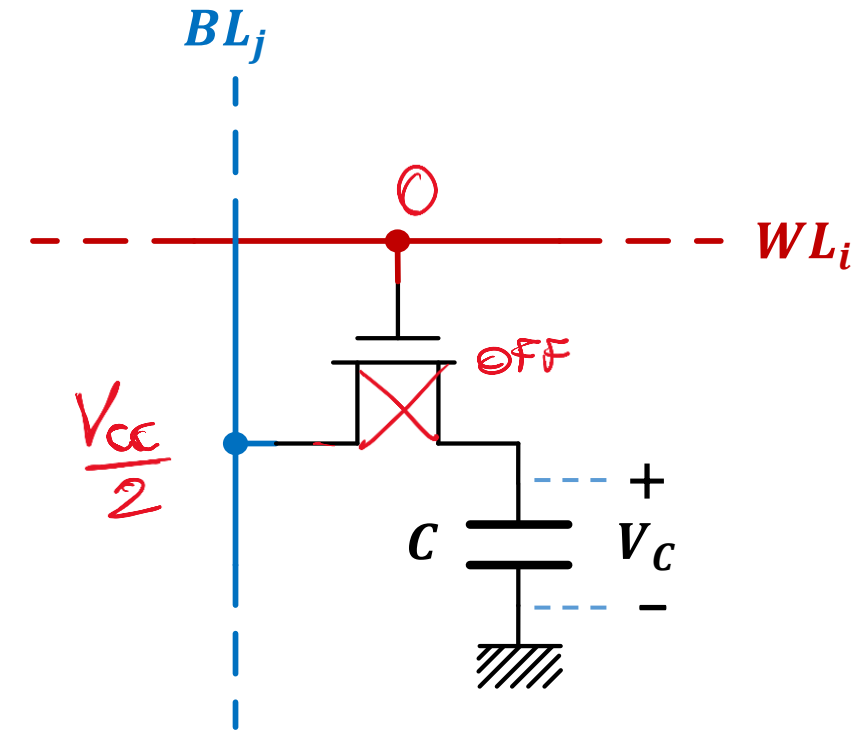
DRAM – Memory cell

- Working principle

- Read

- Step 1

- $WL_i = 0$
- $BL_j = \frac{V_{CC}}{2} = V_R$ (reading voltage)



DRAM – Memory cell

- Working principle

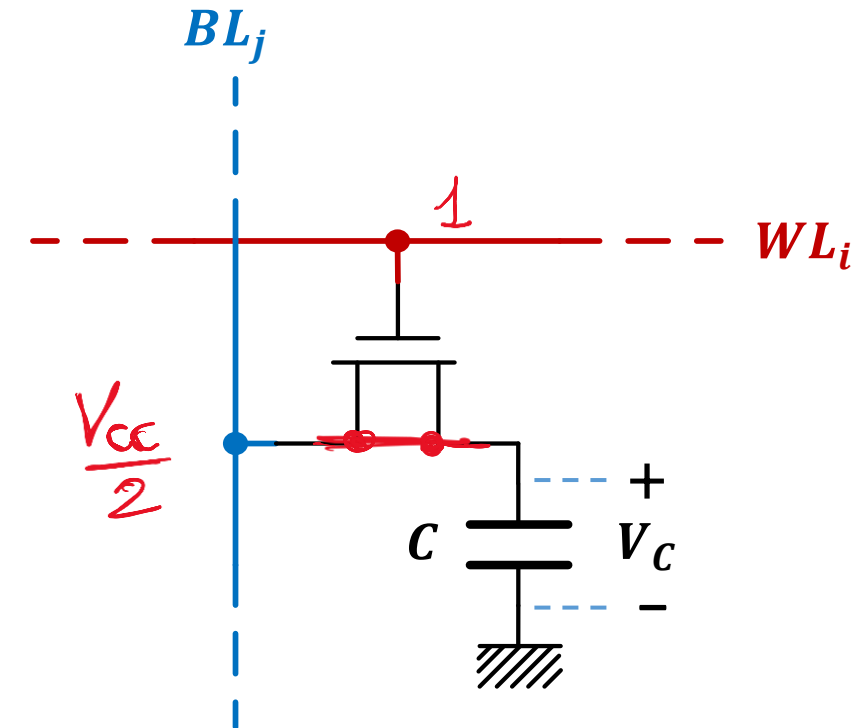
- Read

- Step 1

- $WL_i = 0$
 - $BL_j = \frac{V_{CC}}{2} = V_R$

- Step 2

- $WL_i = 1$



DRAM – Memory cell

- Working principle

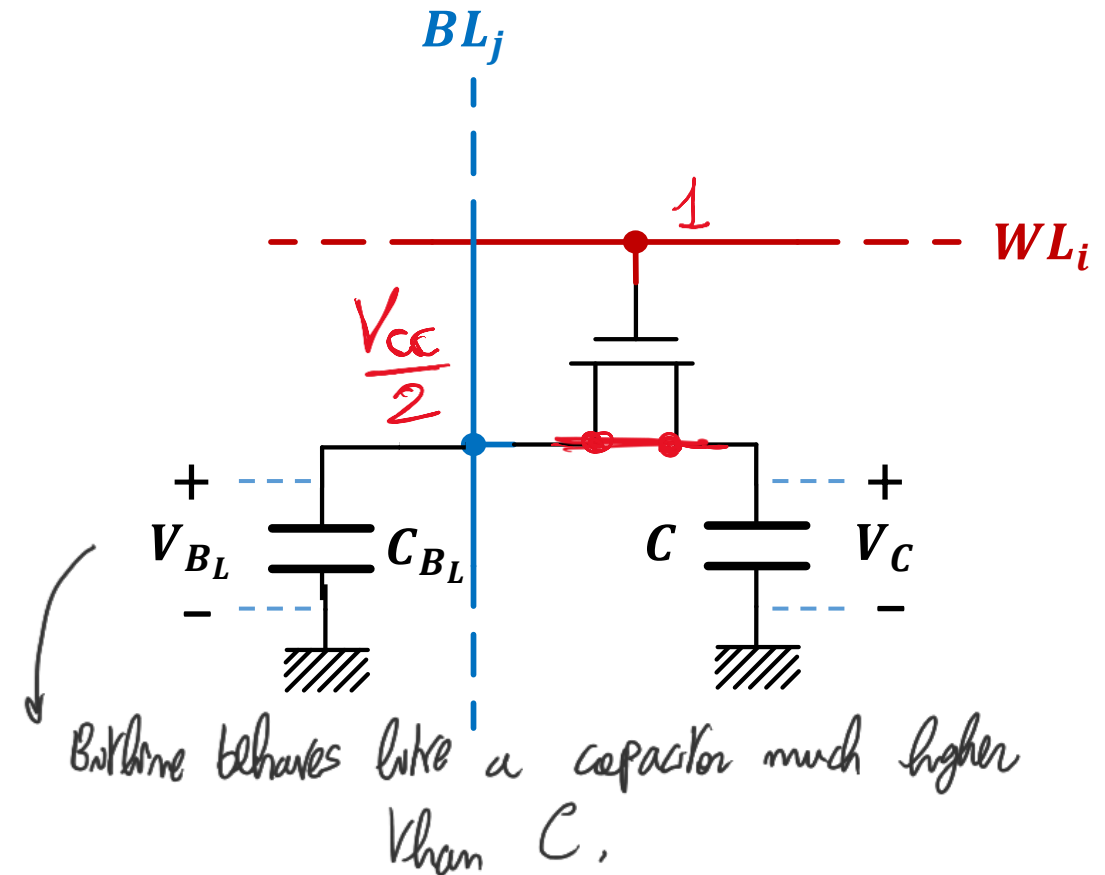
- Read

- Step 1

- $WL_i = 0$
- $BL_j = \frac{V_{CC}}{2} = V_R$

- Step 2

- $WL_i = 1$
- $BL_j \approx C_{BL}$ (capacitor)
 - $C_{BL} \gg C$
 - V_{BL} = voltage on $C_{BL} = \frac{V_{CC}}{2}$

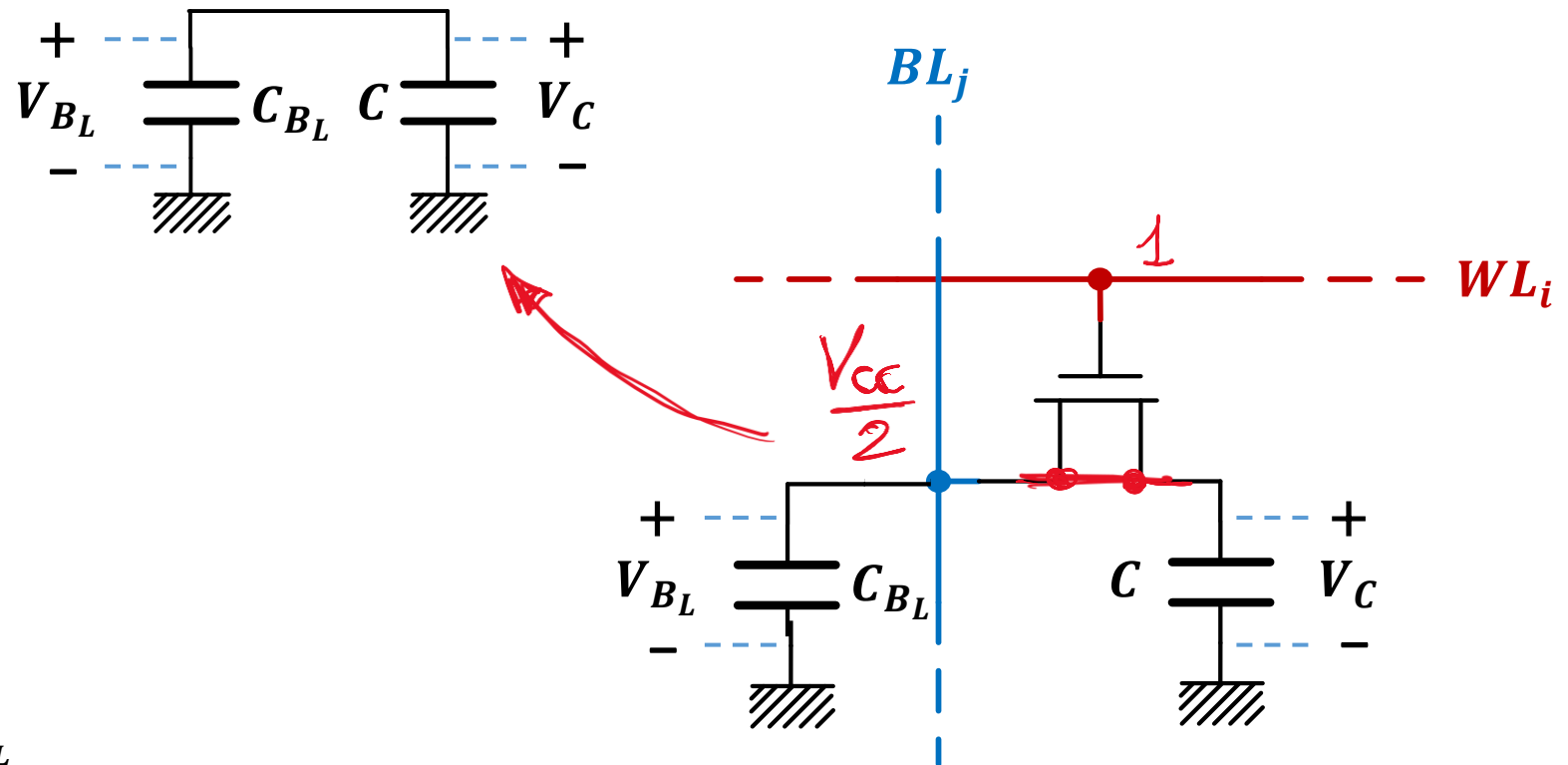


DRAM – Memory cell

- Working principle

- **Read**

- Step 1
 - $WL_i = 0$
 - $BL_j = \frac{V_{CC}}{2} = V_R$
- Step 2
 - $WL_i = 1$
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DRAM – Memory cell

- Working principle

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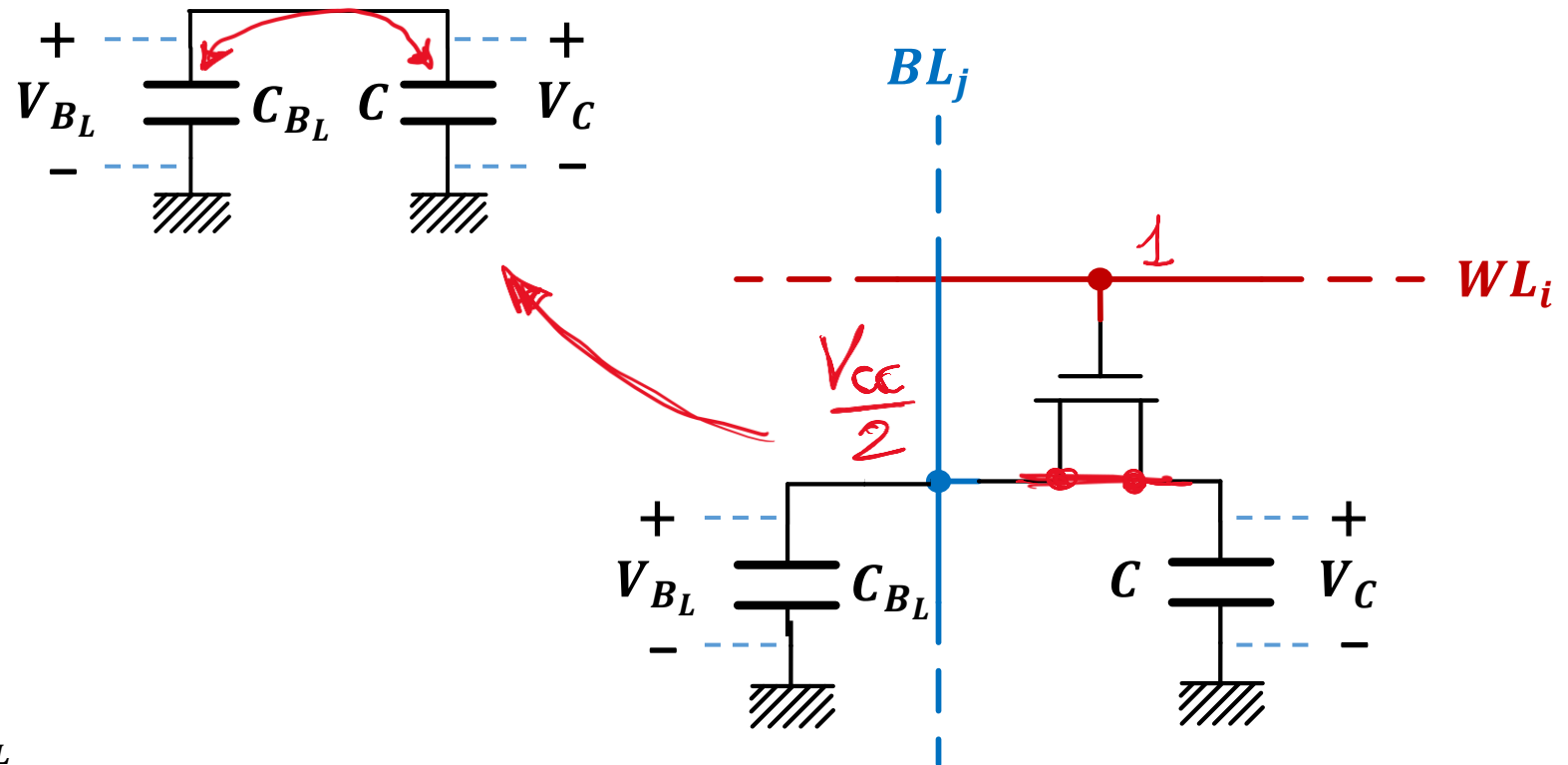
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- $WL_i = 1$
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 - $C_{BL} \gg C$
 - V_{BL} = voltage on C_{BL}

- Charge redistribution between C_{BL} and C !

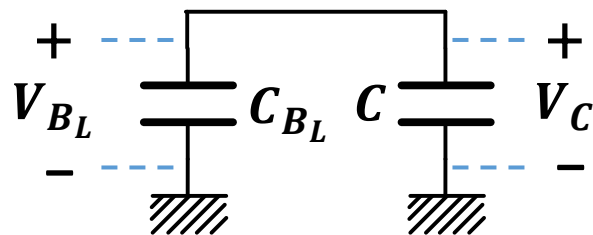


DRAM – Memory cell

- Working principle

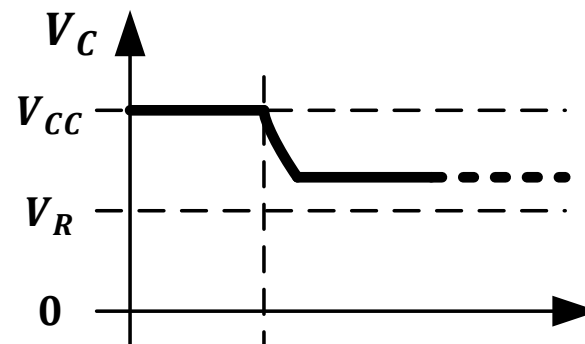
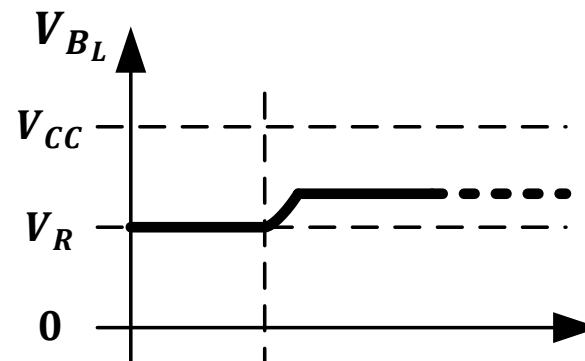
- Read

- Charge redistribution!

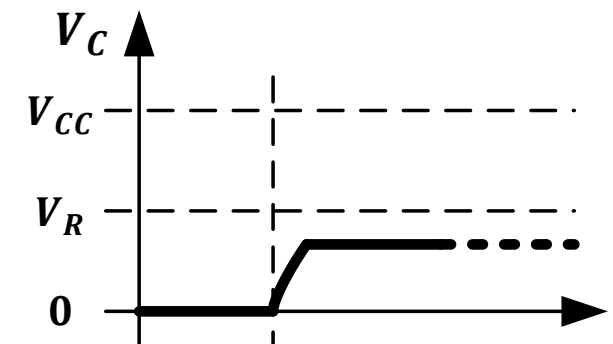
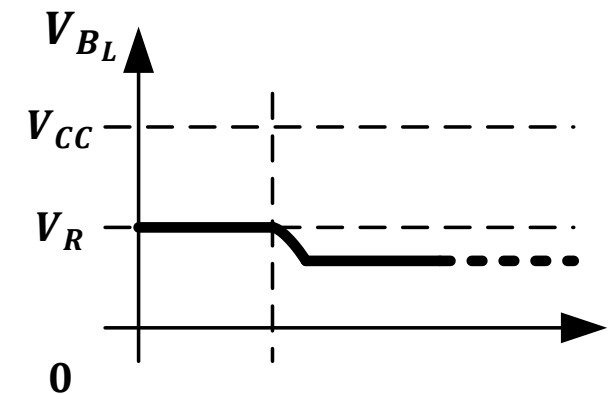


- Read destroys data!
- Need of re-write!

Memory bit = 1 ($V_C = V_{CC}$)



Memory bit = 0 ($V_C = 0 V$)

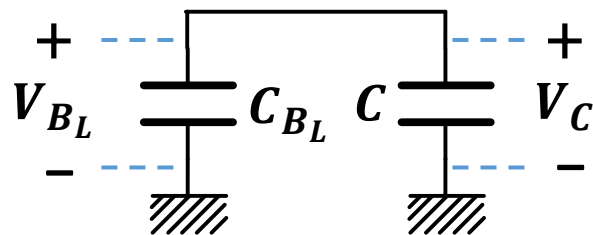


DRAM – Memory cell

- Working principle

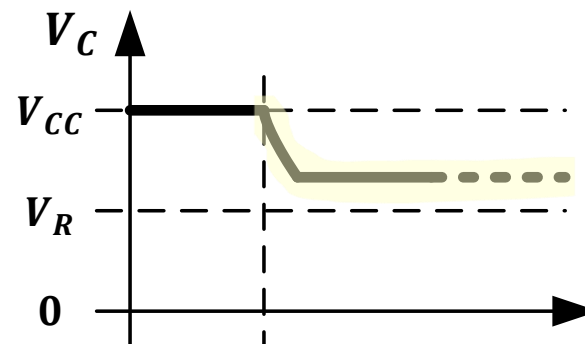
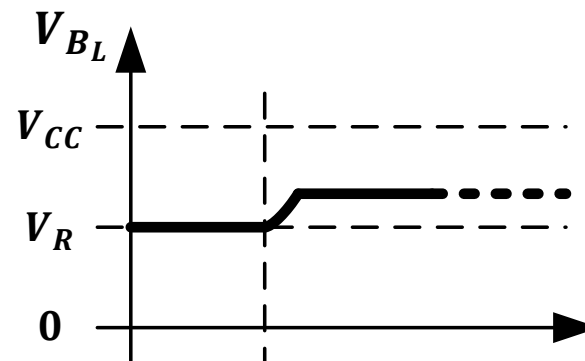
- Read**

- Charge redistribution!

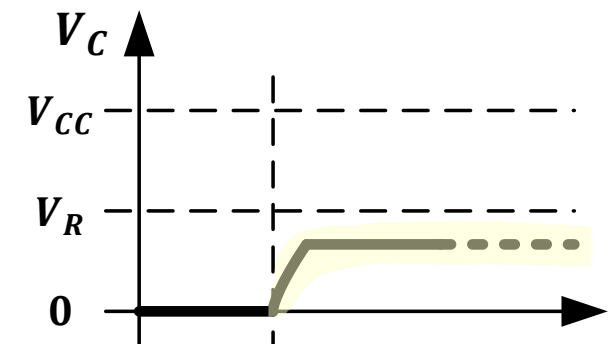
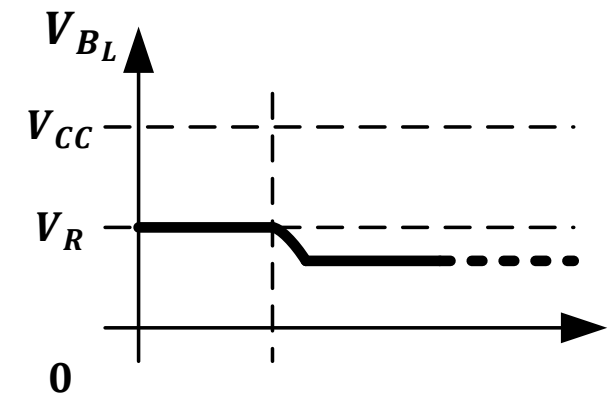


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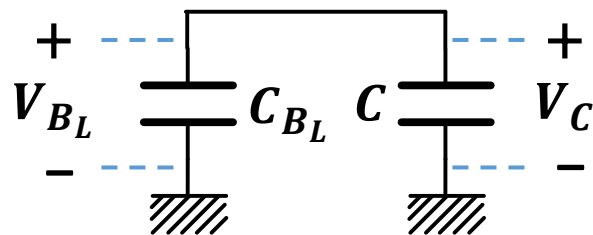


DRAM – Memory cell

- Working principle

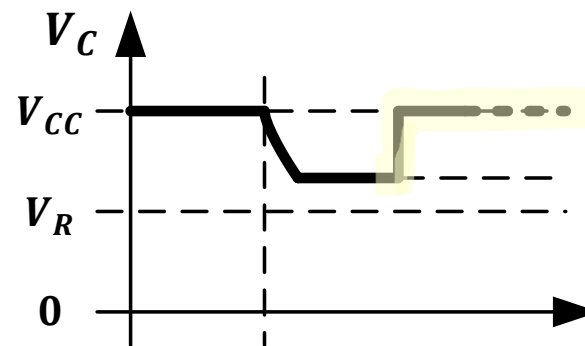
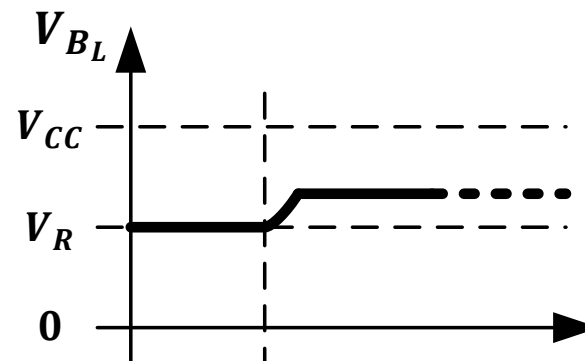
- Read

- Charge redistribution!

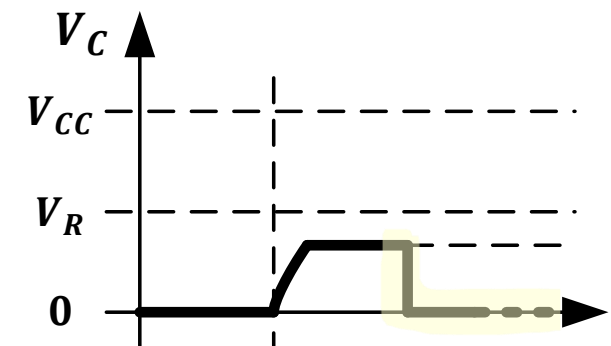
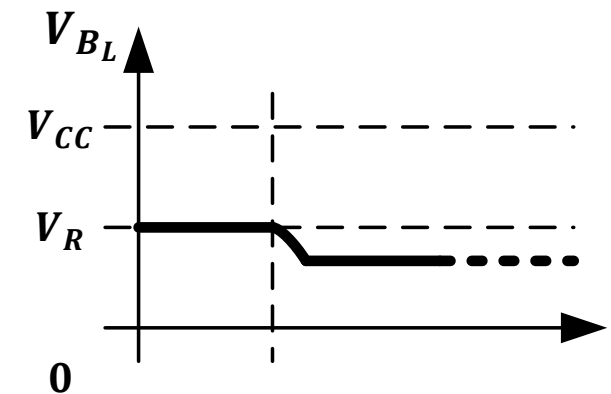


- Read destroys data!
- Need of re-write!

Memory bit = 1 ($V_C = V_{CC}$)



Memory bit = 0 ($V_C = 0 V$)



DRAM – Memory cell

- Working principle

- Read

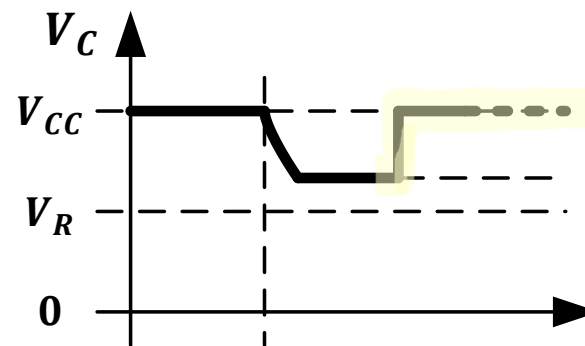
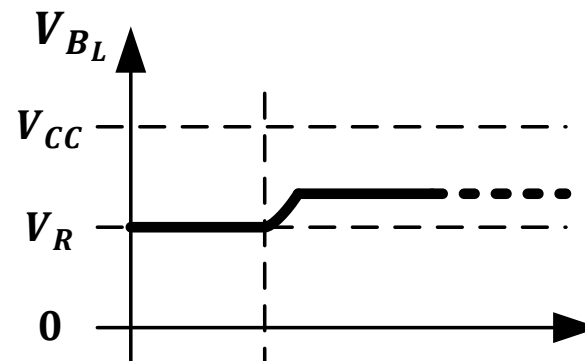
- How to re-write?

- If $V_{BL} > V_R \rightarrow 1$

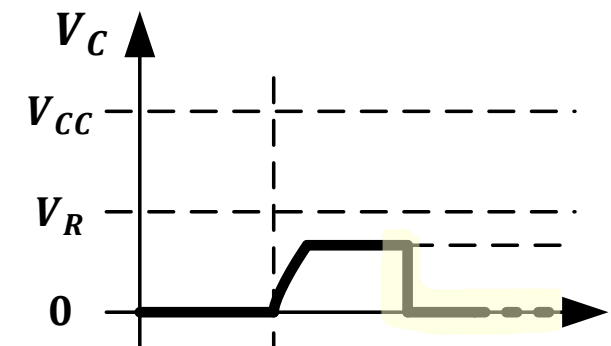
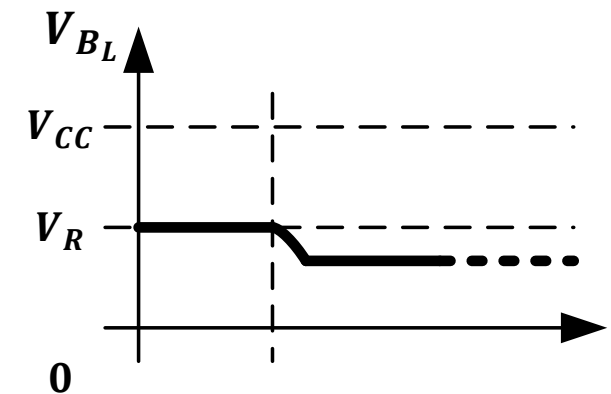
- If $V_{BL} < V_R \rightarrow 0$

If voltage is higher
means I had a
logic 1.

Memory bit = 1 ($V_C = V_{CC}$)



Memory bit = 0 ($V_C = 0 V$)



DRAM – Memory cell

• Working principle

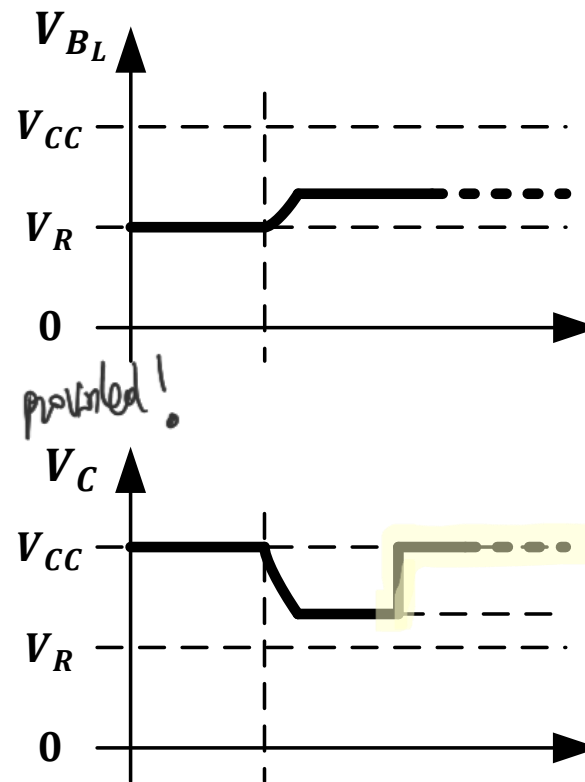
• Read

■ How to re-write?

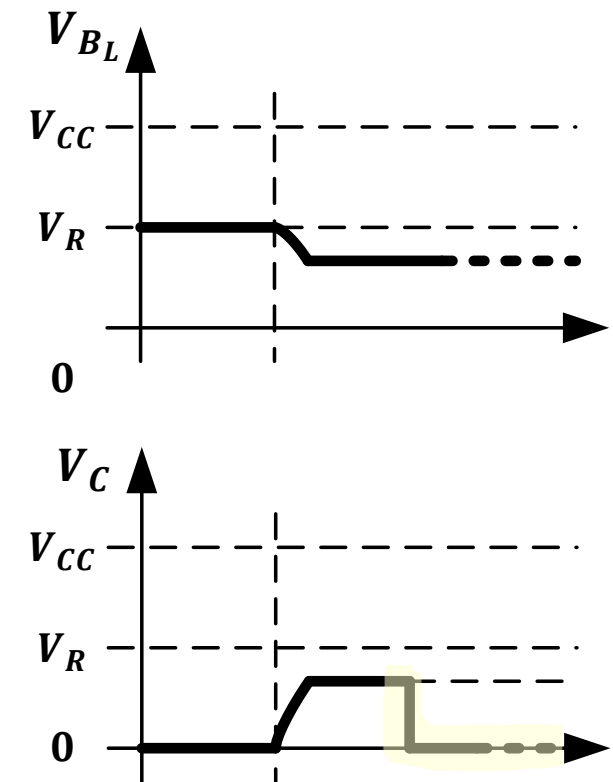
- If $V_{BL} > V_R \rightarrow 1$
- If $V_{BL} < V_R \rightarrow 0$

- $|V_{BL} - V_R|$ *Amplify the difference provided!*
 - Very small value
 - Must be amplified!

Memory bit = 1 ($V_C = V_{CC}$)



Memory bit = 0 ($V_C = 0 V$)



DRAM – Memory cell

- Working principle

- Read

- How to re-write?

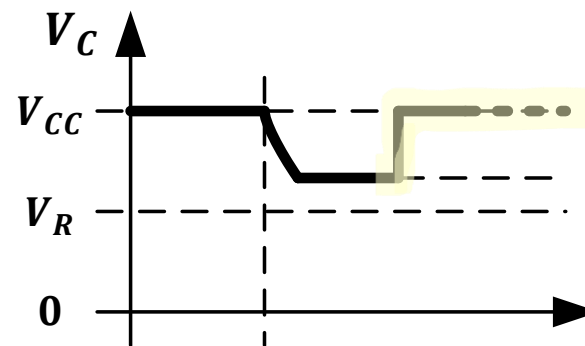
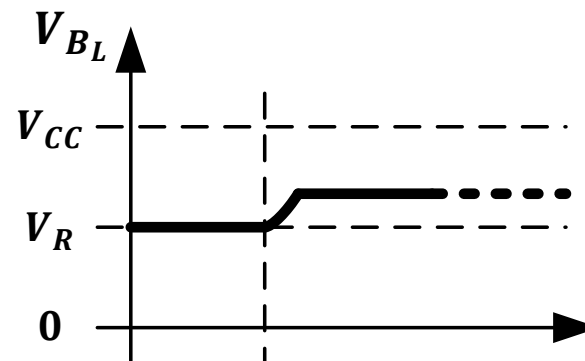
- If $V_{BL} > V_R \rightarrow 1$
- If $V_{BL} < V_R \rightarrow 0$

- $|V_{BL} - V_R|$

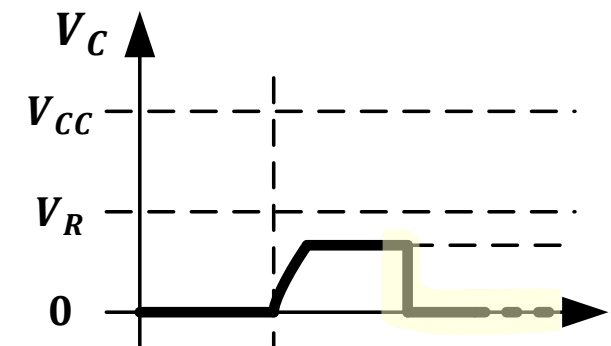
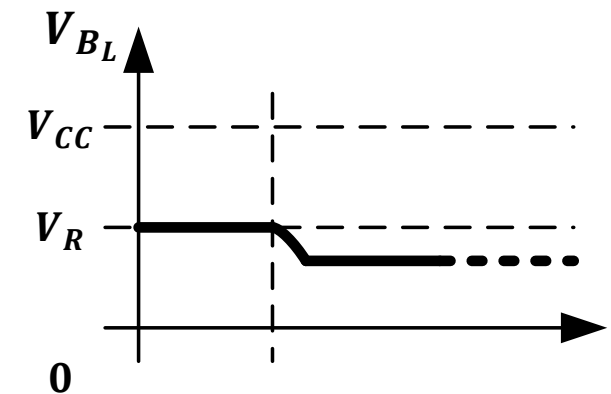
- Very small value
- Must be amplified!

- Sense Amplifier (SA)

Memory bit = 1 ($V_C = V_{CC}$)

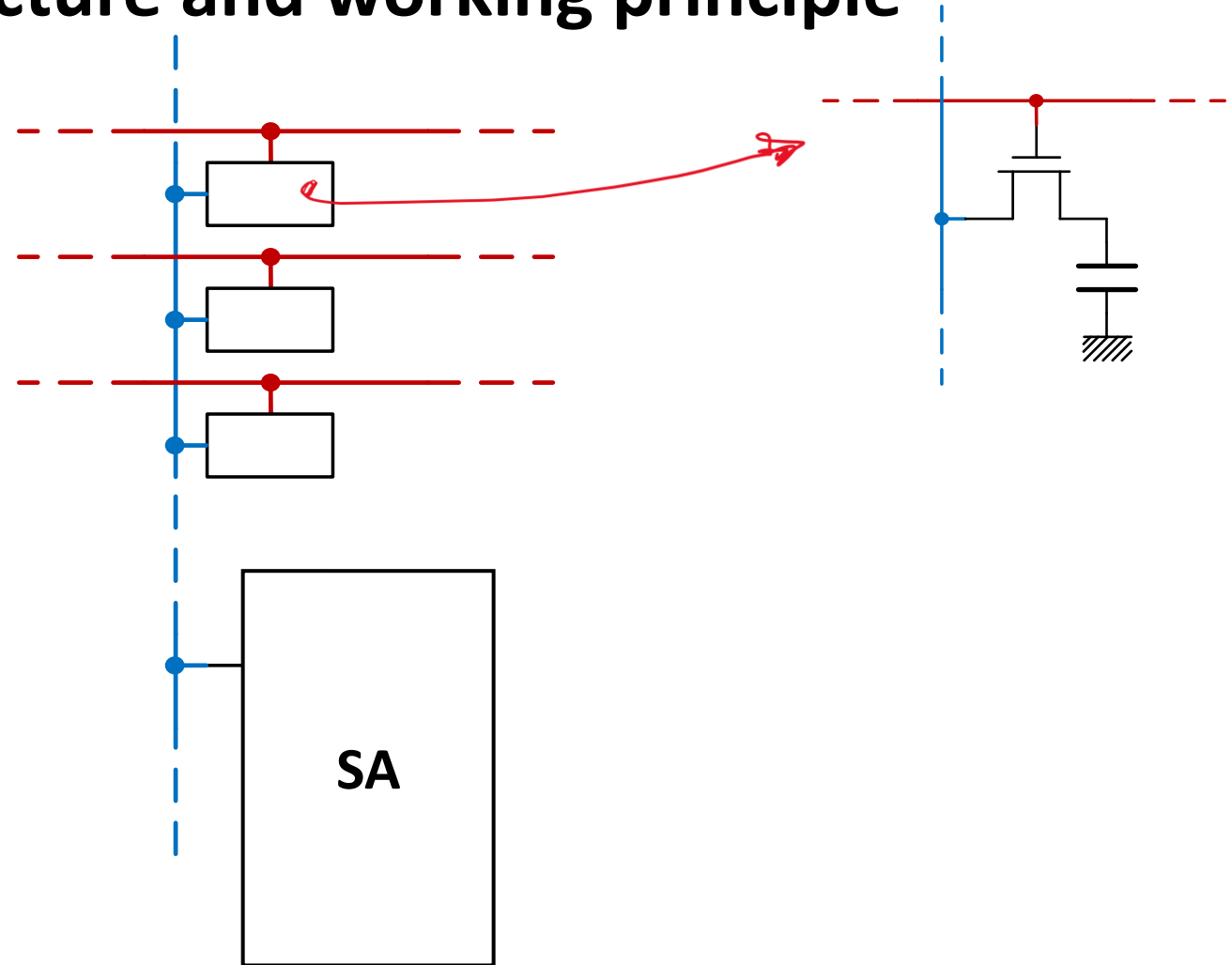


Memory bit = 0 ($V_C = 0 V$)



DRAM – Architecture and working principle

- Draft
 - **Sense Amplifier (SA)**



DRAM – Architecture and working principle

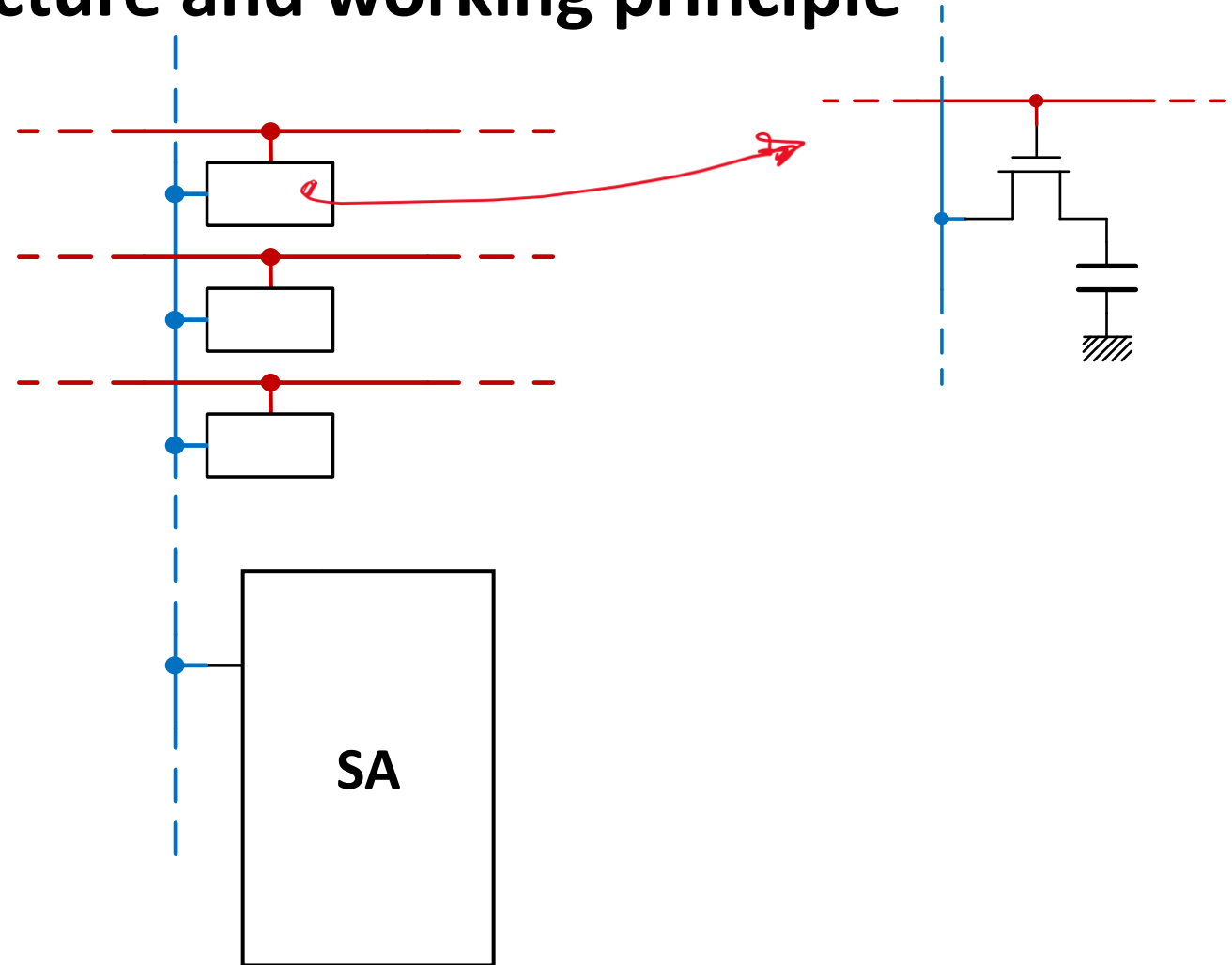
- Draft

- Sense Amplifier (SA)

- How?

- **Bistable** !

- We have already seen in SRAM



DRAM – Architecture and working principle

- Draft

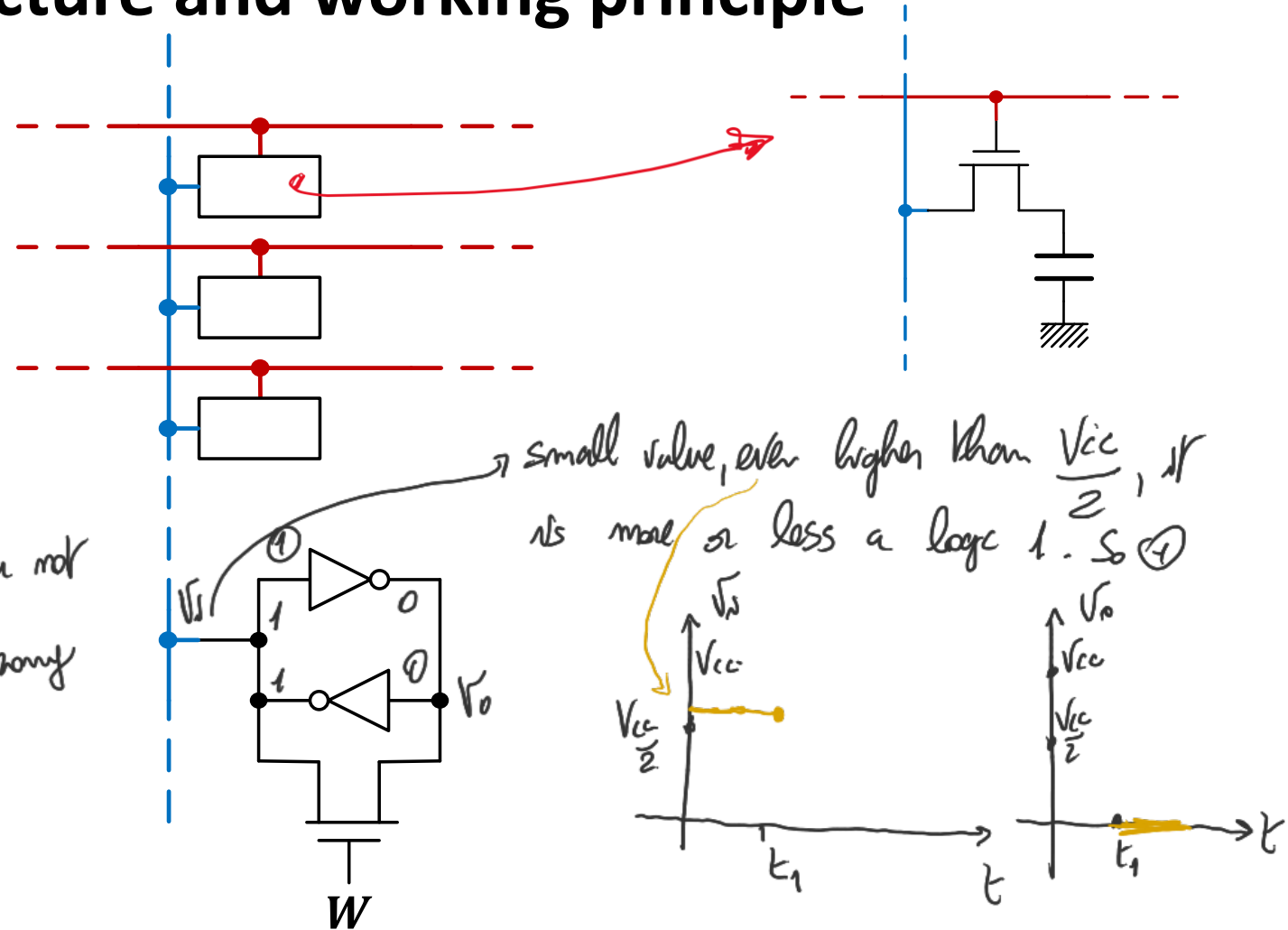
- Sense Amplifier (SA)

- How?

- **Bistable !**

- We have already seen in SRAM

You will have a strong logic 0 even with a not strong 1. A strong logic 0 regenerates a strong logic 1.



DRAM – Architecture and working principle

- Draft

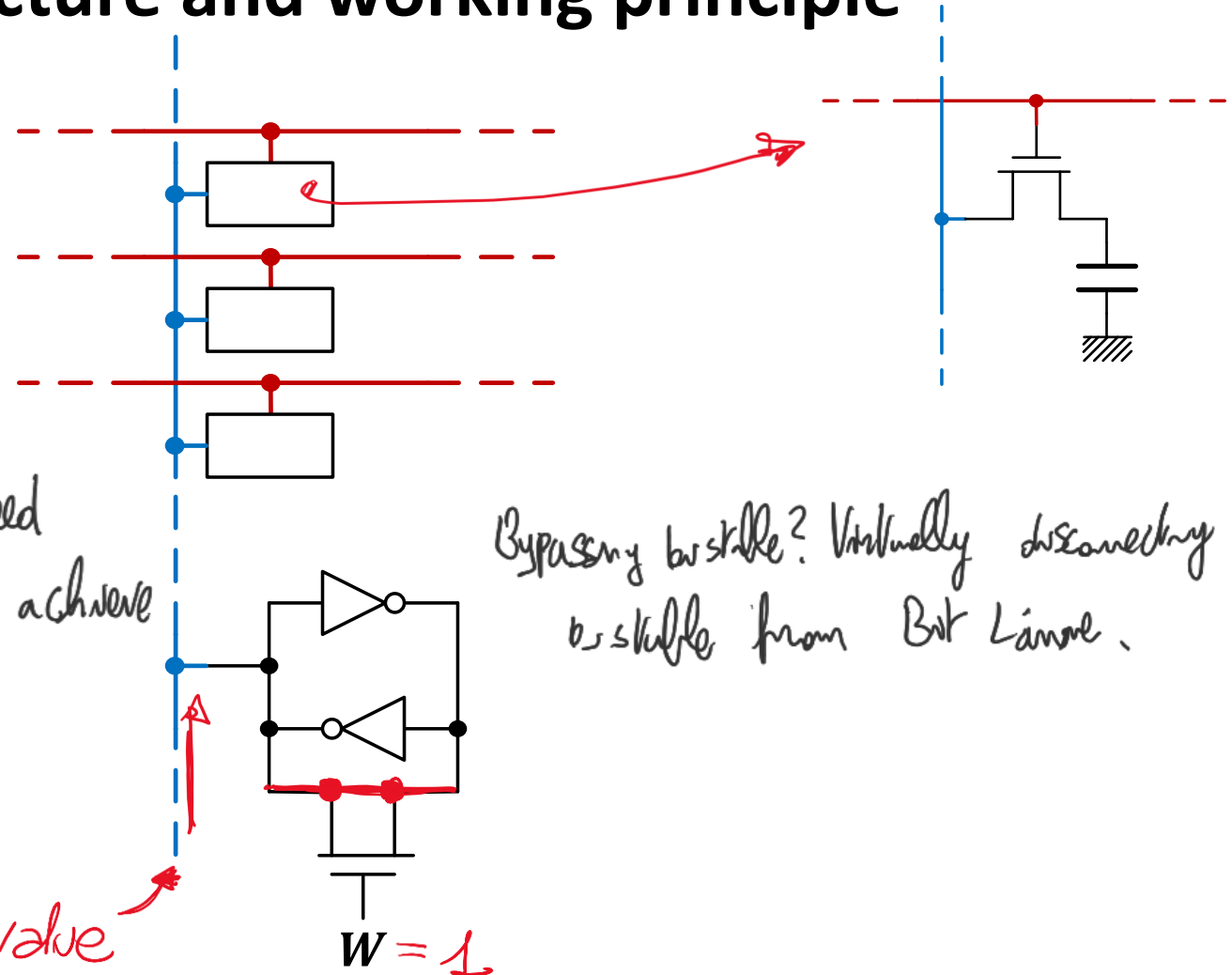
- Sense Amplifier (SA)

- **Write ($W = 1$)**

- Bistable is bypassed (OFF)
 - Write value on Bit Line

When we want to write, we need to force disconnection to achieve writing.

write value



DRAM – Architecture and working principle

- Draft

- Sense Amplifier (SA)

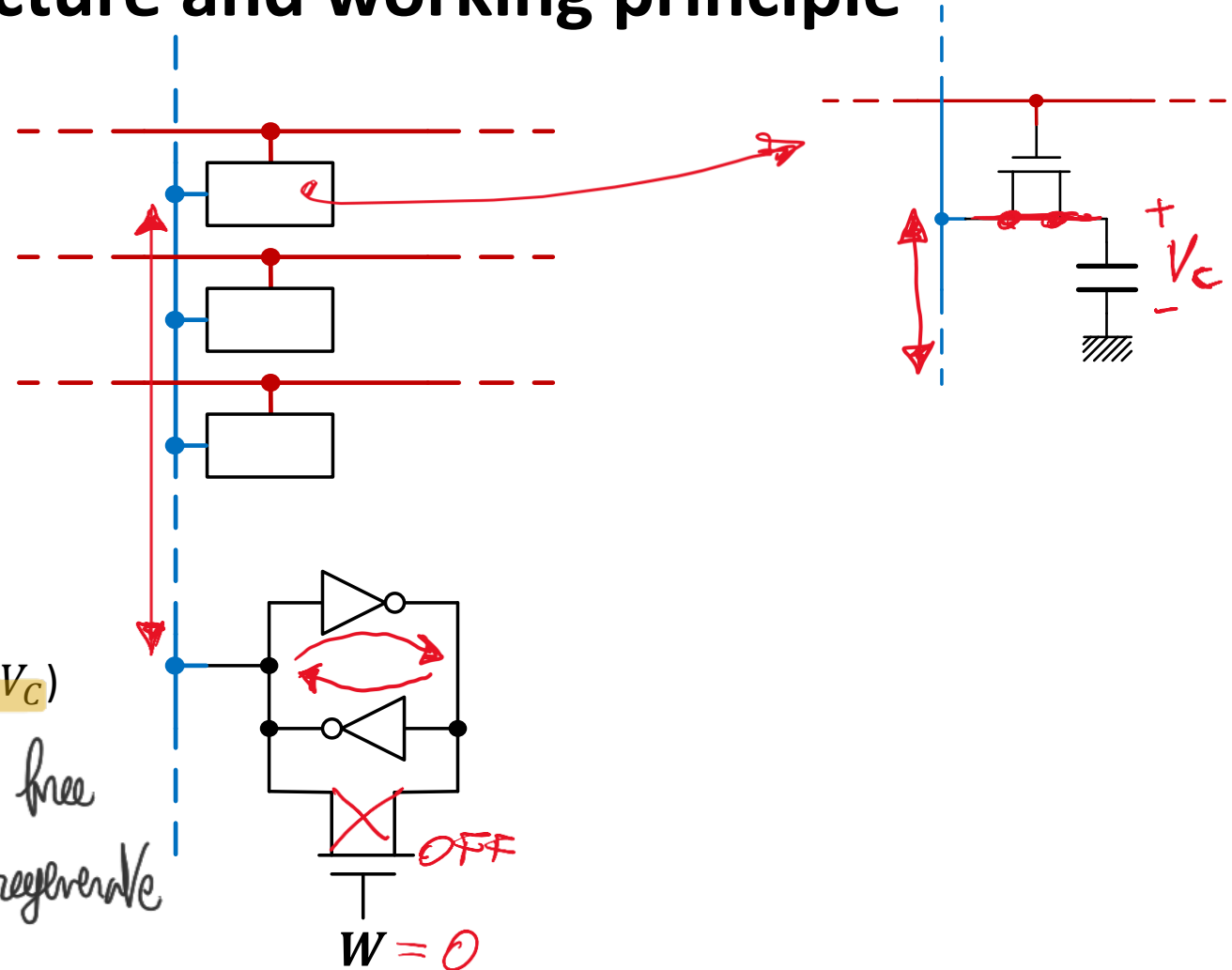
- Write ($W = 1$)

- Bistable is bypassed (OFF)
 - Write value on Bit Line

- Read ($W = 0$)

- Bistable is ON
 - Bistable regenerates memory bit (V_C)

↳ here the bistable is free
to evolve and regenerate



DRAM – Architecture and working principle

- Draft

- Bit Lines are “big” capacitors (C_{BL})

- SAs placed in the middle (of each BL) for balancing capacitive load (C_{BL})

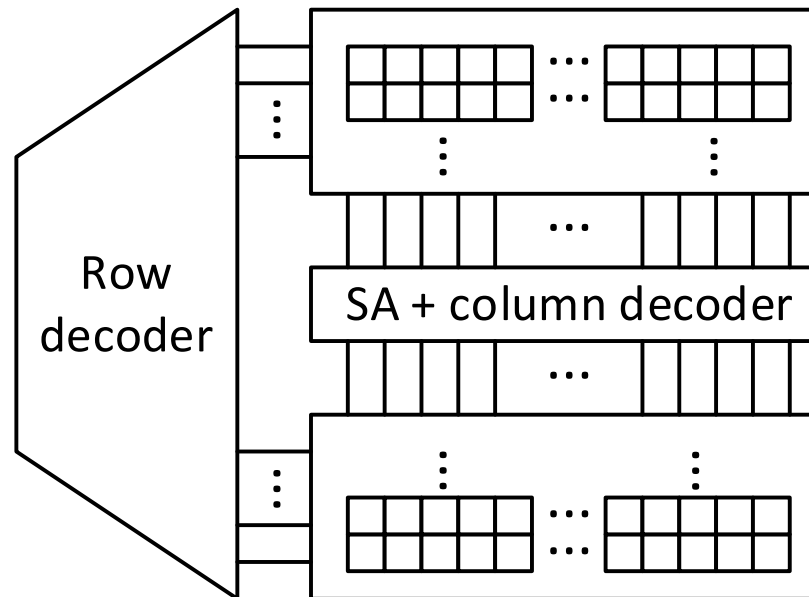
→ To have capacity seen by the input of the SA be the same in both directions.

- In addition

- SA block merged with the column-decoder for resource saving and architecture simplification

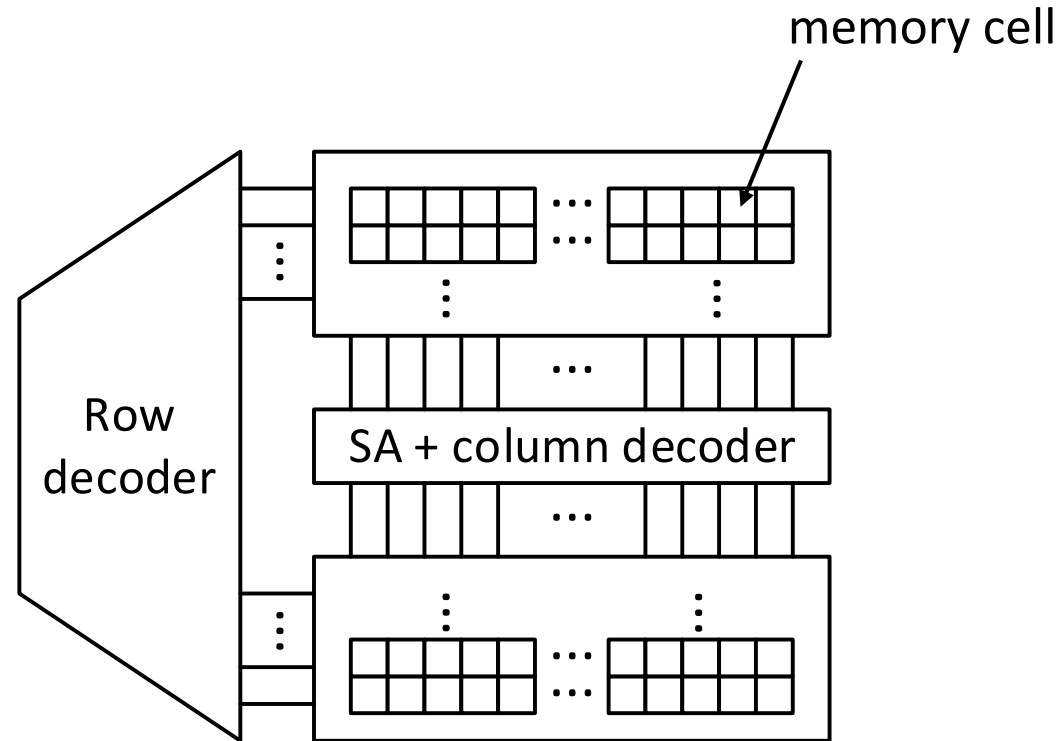
DRAM – Architecture and working principle

- Draft



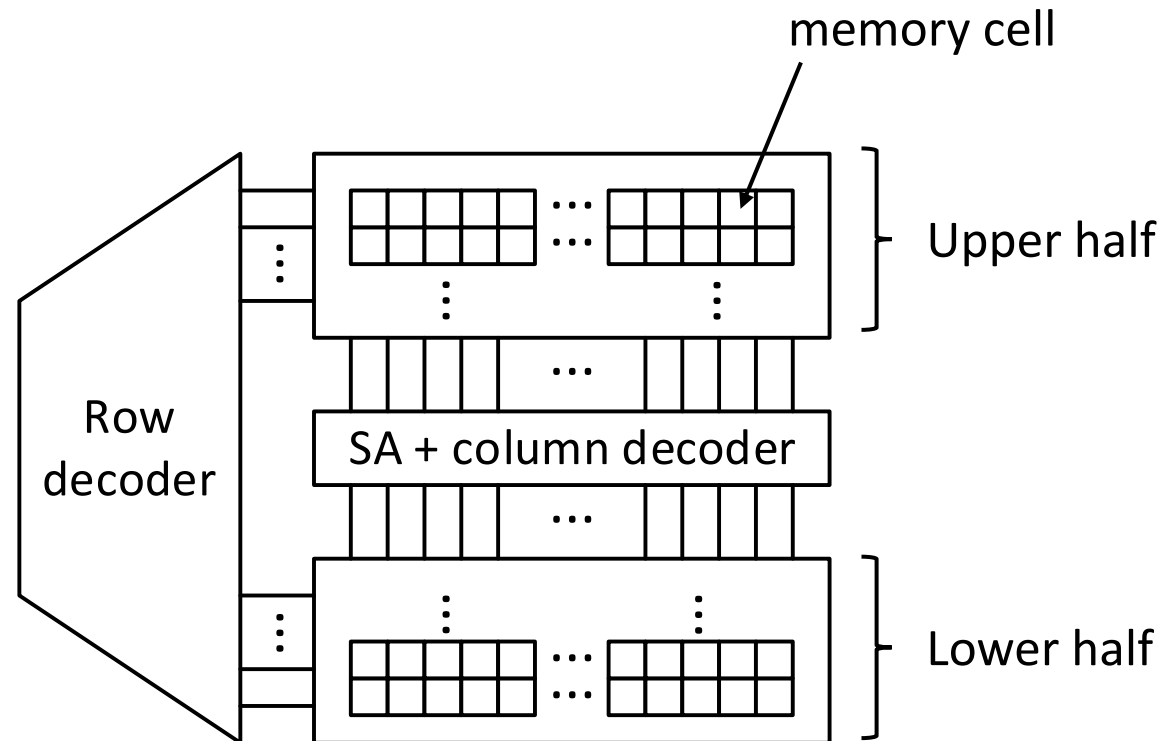
DRAM – Architecture and working principle

- Draft



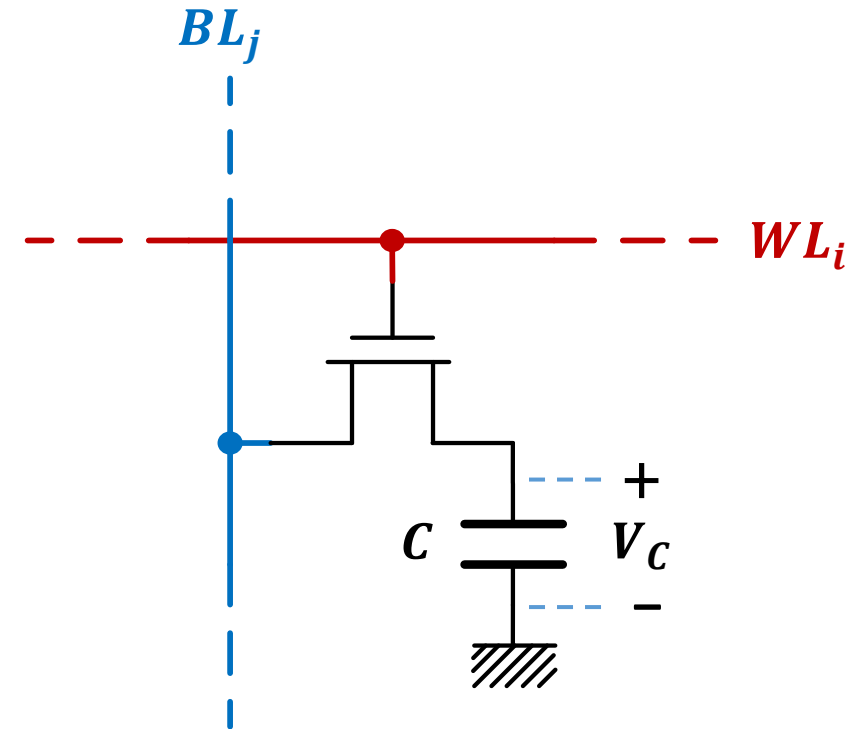
DRAM – Architecture and working principle

- Draft



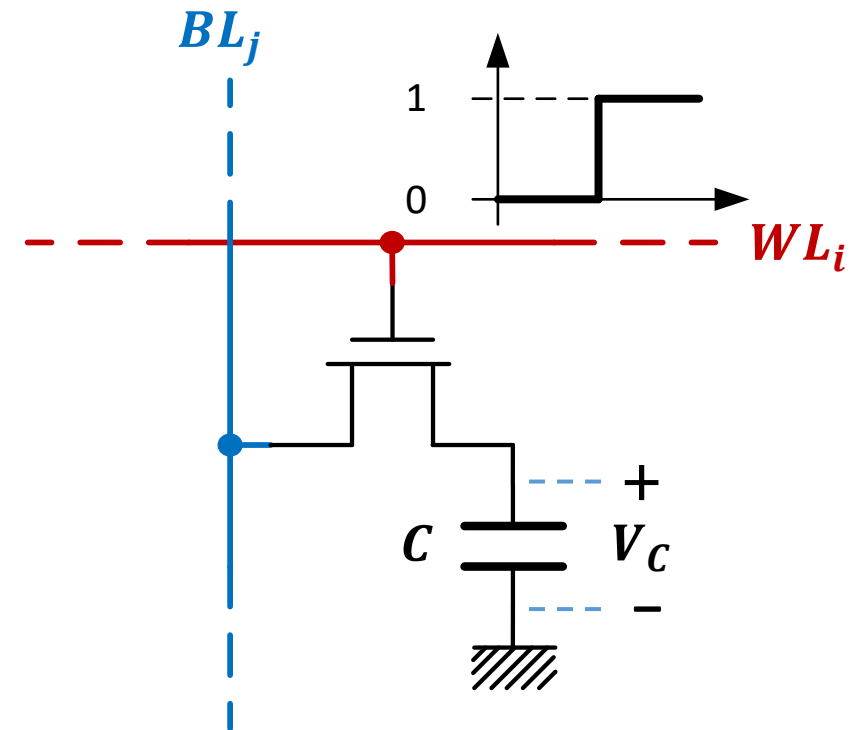
DRAM – Architecture and working principle

- Draft
 - Other problem(s)
 - When reading (or writing)
 - WL_i moves from 0 to 1



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 - Other problem(s)
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- Draft

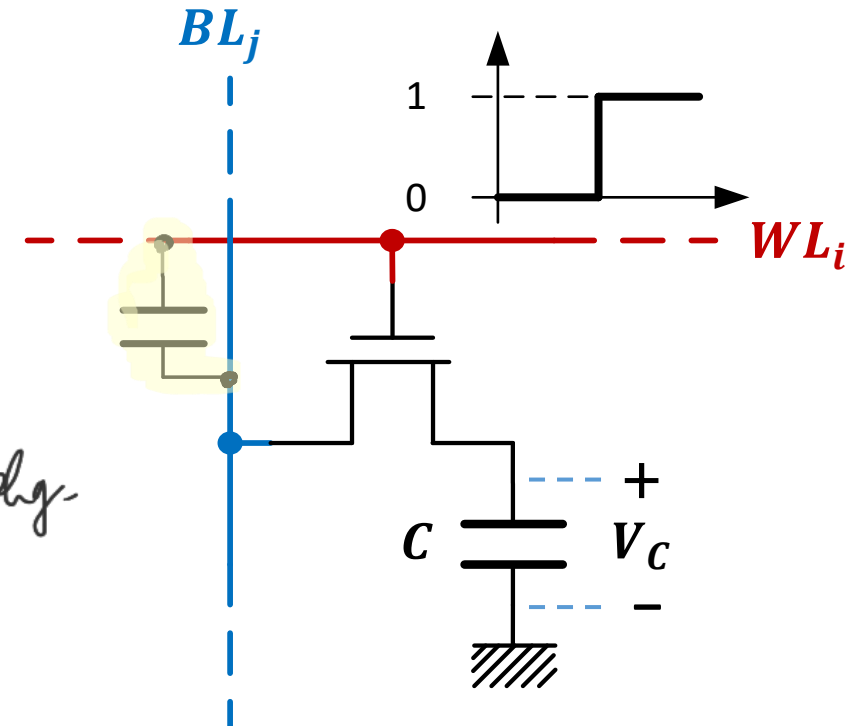
- Other problem(s)

- When reading (or writing)

- WL_i moves from 0 to 1

- Capacitive coupling between WL_i and BL_j

↓ This behaves like capacitive coupling.



DRAM – Architecture and working principle

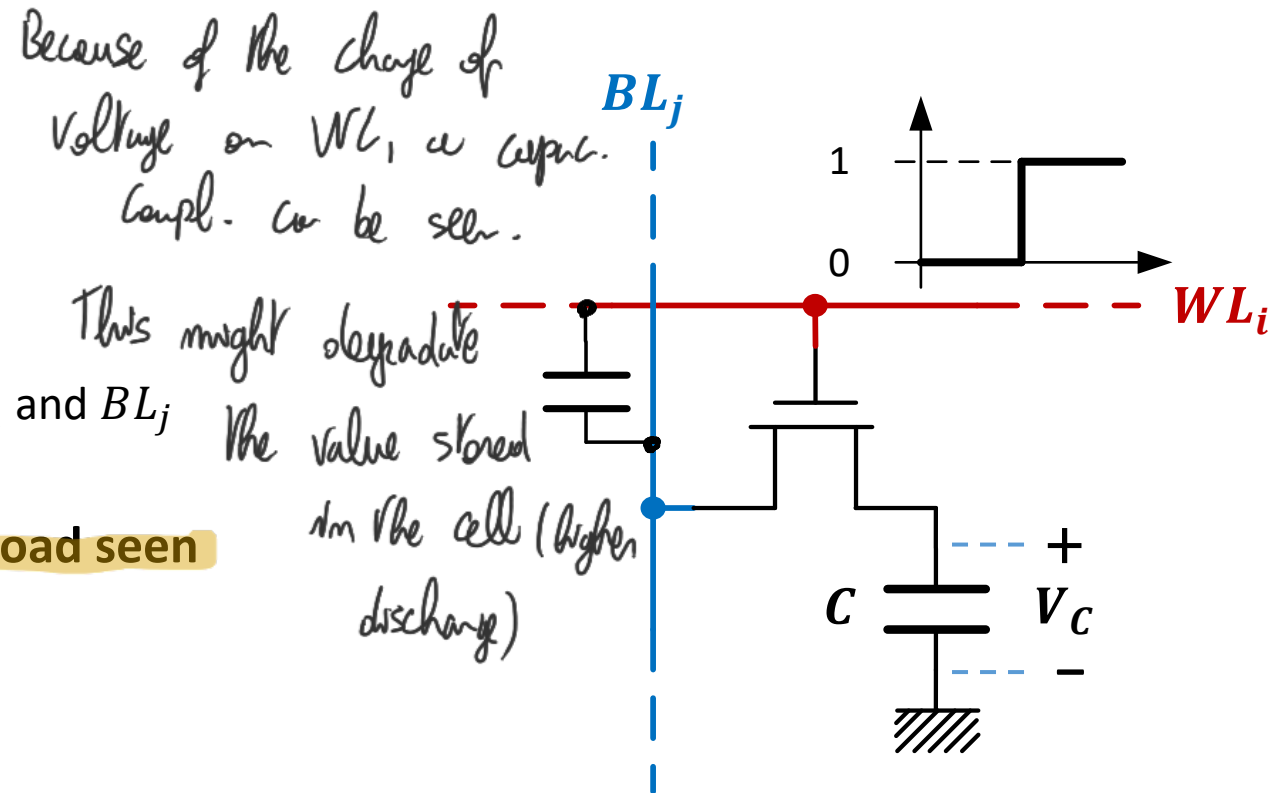
- Draft

- Other problem(s)

- When reading (or writing)

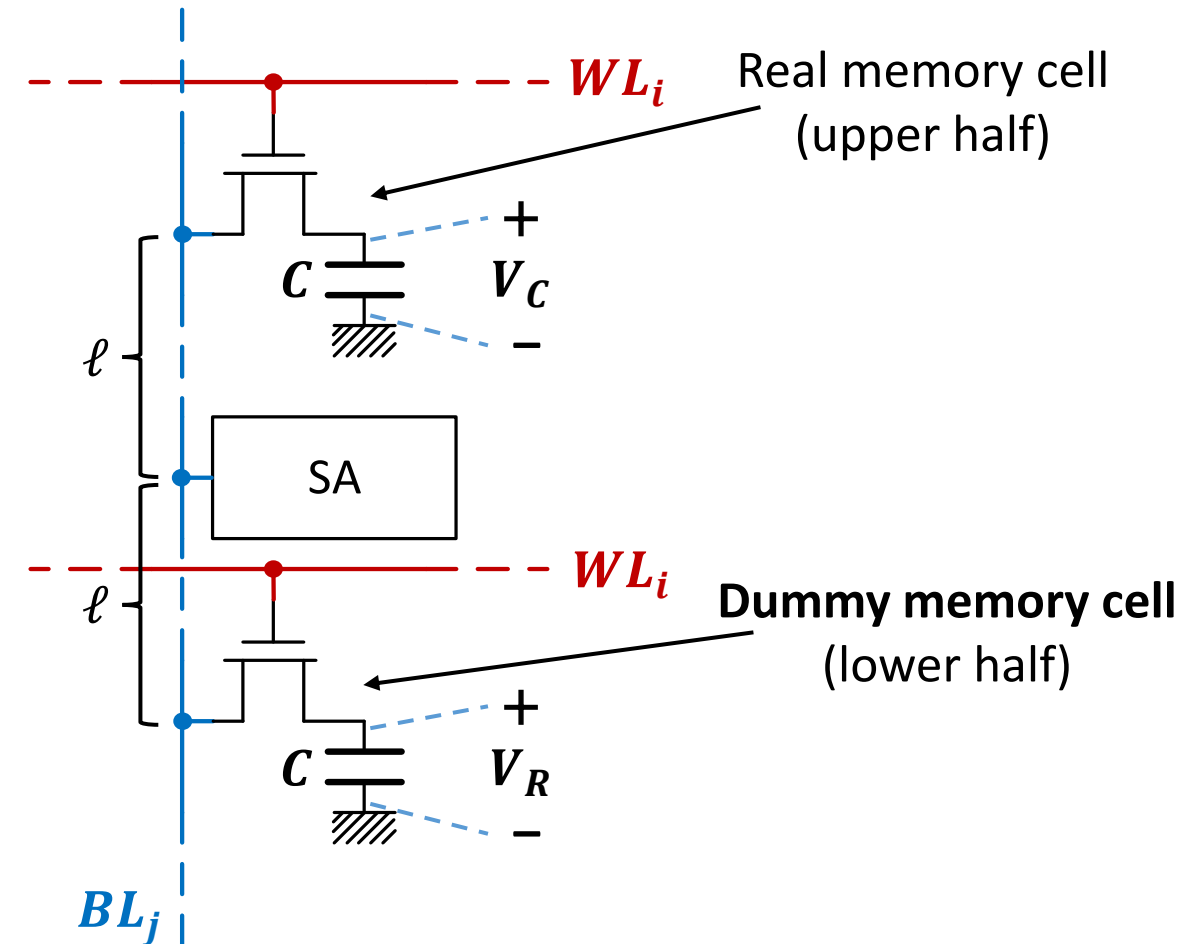
- WL_i moves from 0 to 1
 - Capacitive coupling between WL_i and BL_j

- To counteract this, the capacitive load seen by the SA must be balanced !



DRAM – Architecture and working principle

- Draft
 - Balancing capacitive load seen by SA
 - Same distance ℓ in opposite directions
 - Same WL_i
 - Dummy memory cell
 - Opposite half
 - Preloaded at V_R





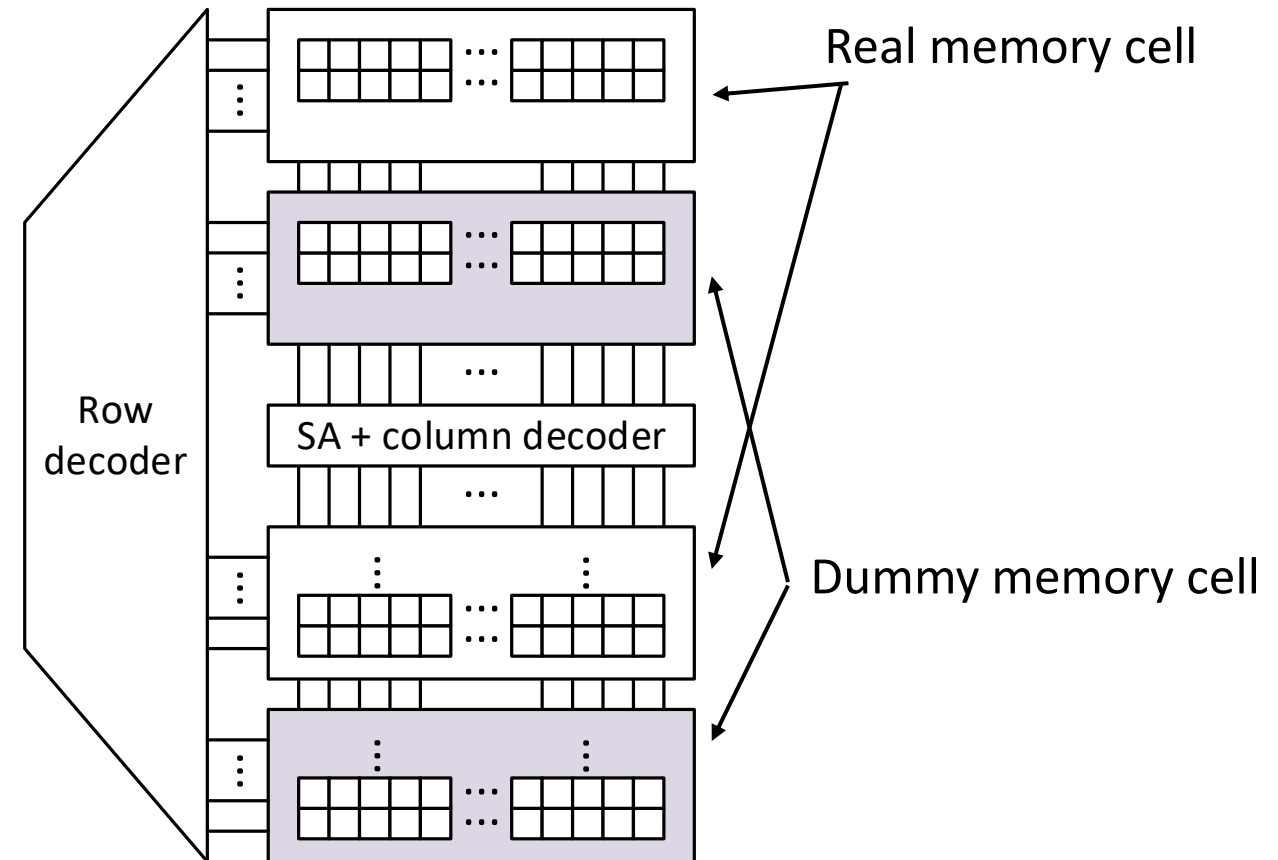
If you are doing nothing, capacity level seen by the SA up and down is the same. Now assume that you connect one memory cell, this means that capacity level on the top is more than the one we see down.

When you do any kind of operation (activating the function of the cell) this is a connection.

To balance this imbalance we need a dummy cell. It is connected to the
SAME WORDLINE

DRAM – Architecture and working principle

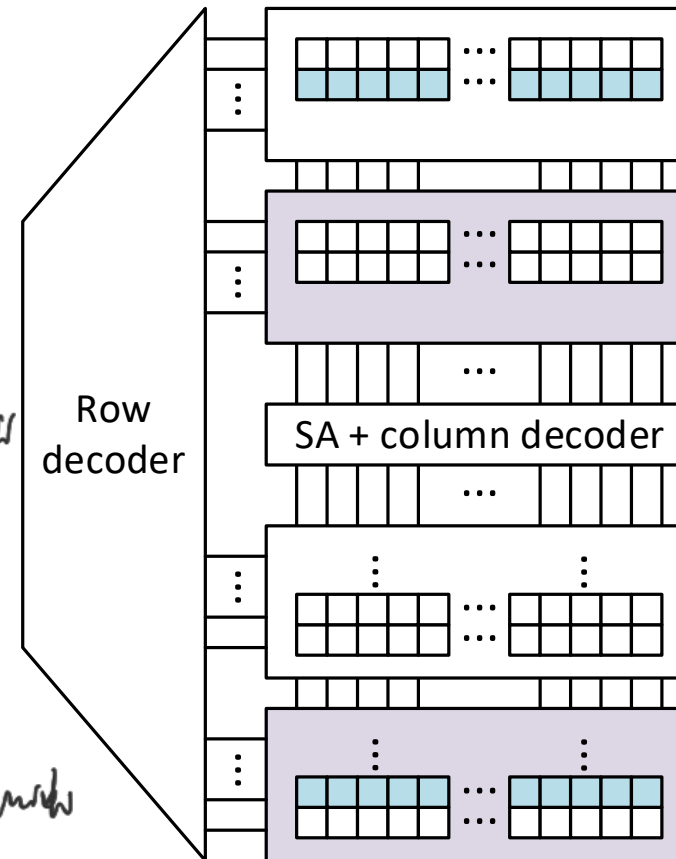
- Draft
 - Including dummy cells



DRAM – Architecture and working principle

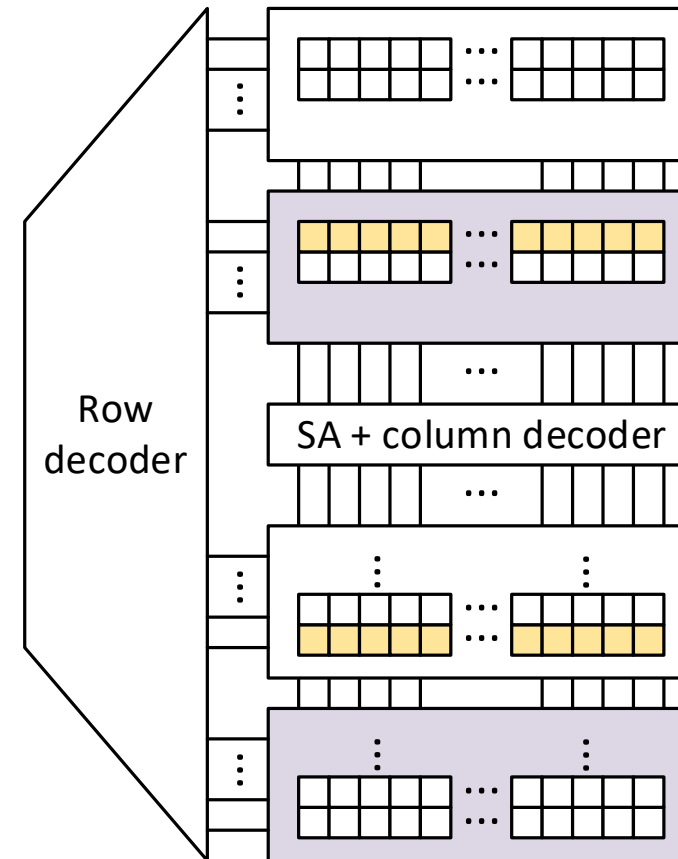
- Draft
 - Including dummy cells
 - Example
 - Balancing **upper** half

Differenza per n 2 caschi capacitor per la una differenza letture tra n due caschi diversi e quindi non va bene



DRAM – Architecture and working principle

- Draft
 - Including dummy cells
 - Example
 - Balancing **lower** half



DRAM – Architecture and working principle

- Final
 - To complete the architecture, they should be integrated
 - Address
 - Write command/signal
 - Input data (D) and output data (Q) ports

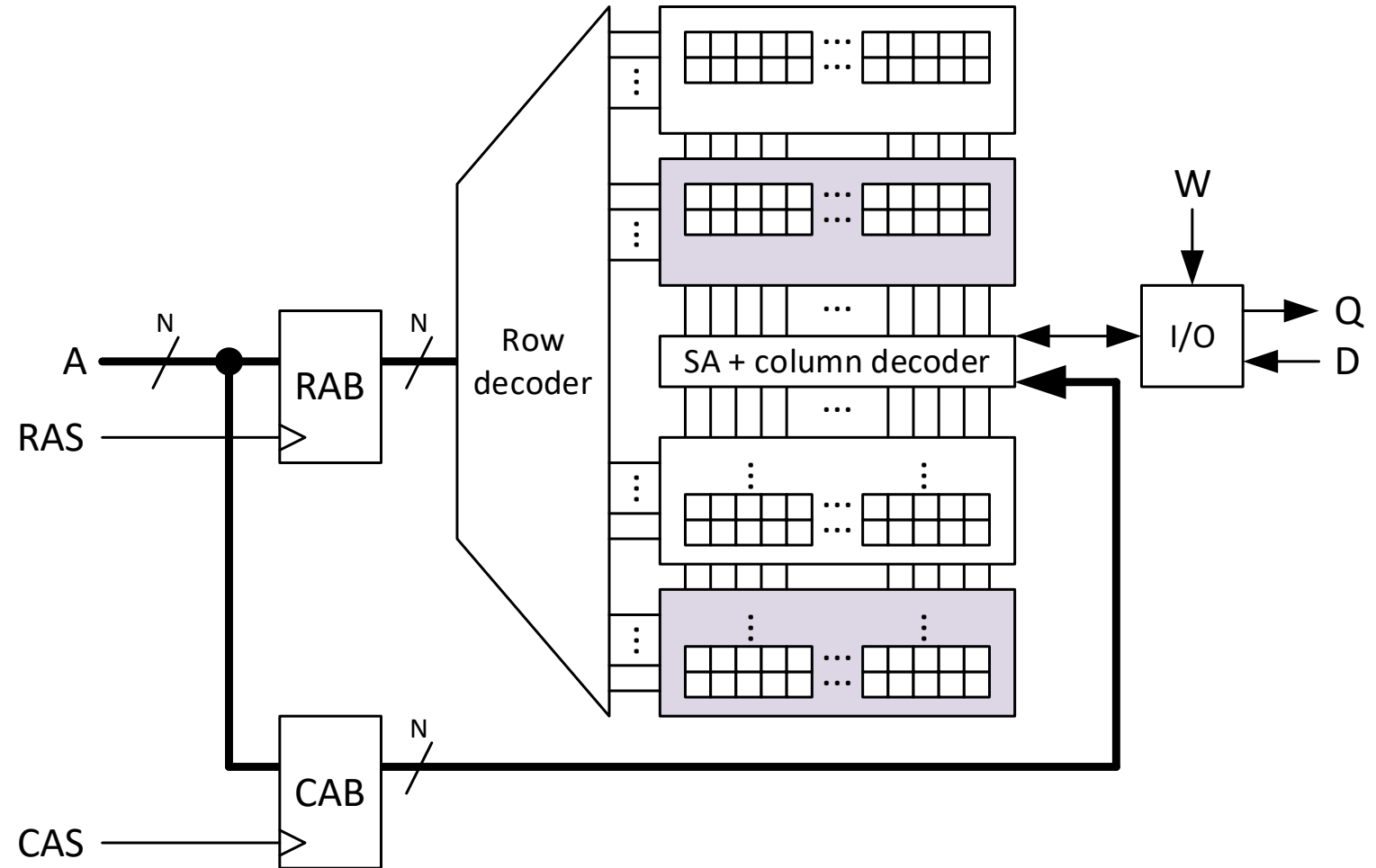
DRAM – Architecture and working principle

- Final
 - To complete the architecture, they should be integrated
 - Address
 - Write command/signal
 - Input data (D) and output data (Q) ports
 - To reduce costs/save resources
 - Single I/O port
 - Single address port shared by row and column decoders
 - Buffer to store row/column address
 - **RAB = Row Address Buffer** ← triggered by signal **RAS = Row Address Strobe**
 - **CAB = Column Address Buffer** ← triggered by signal **CAS = Column Address Strobe**

DRAM – Architecture and working principle

- Final

- A = address port
- Q = output (data) port
- D = input (data) port
- W = write command



DRAM – Architecture and working principle

- Memory bit stored inside the cells lasts at most 10 – 100 *ms*

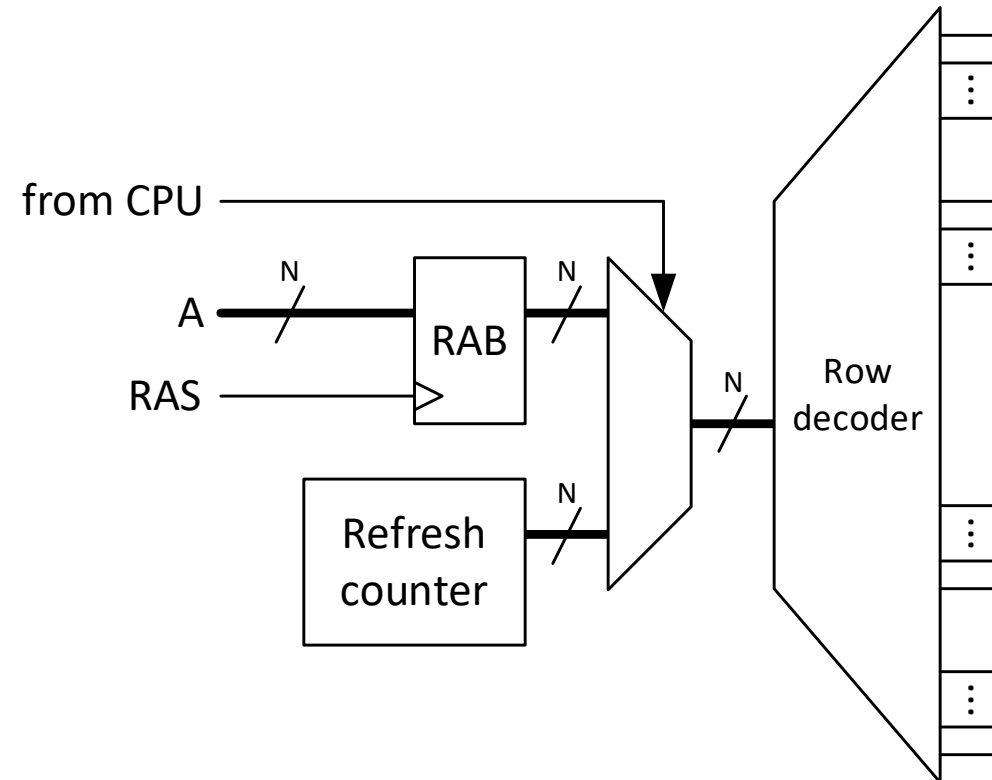
- **REFRESH** operation is required

We need to precharge BLs $16 \frac{V_{cc}}{2}$ times

- Only row must be addressed to refresh the memory
 - All cells in the same row (Word Line) can be refreshed at the same time
- T_{REF} = maximum time before refresh
- Different approaches
 - Wait for T_{REF} and then refresh all memory rows *in sequence*
 - Wait for $\frac{T_{REF}}{\text{row number}}$ and refresh one row at a time

DRAM – Architecture and working principle

- Memory bit stored inside the cells lasts at most 10 – 100 *ms*
 - **REFRESH** operation is required
 - DRAM “knows” **where** (which row) to perform the refresh
 - Counter
 - Processor/CPU “knows” **when** to perform the refresh
 - Timer



SDRAM

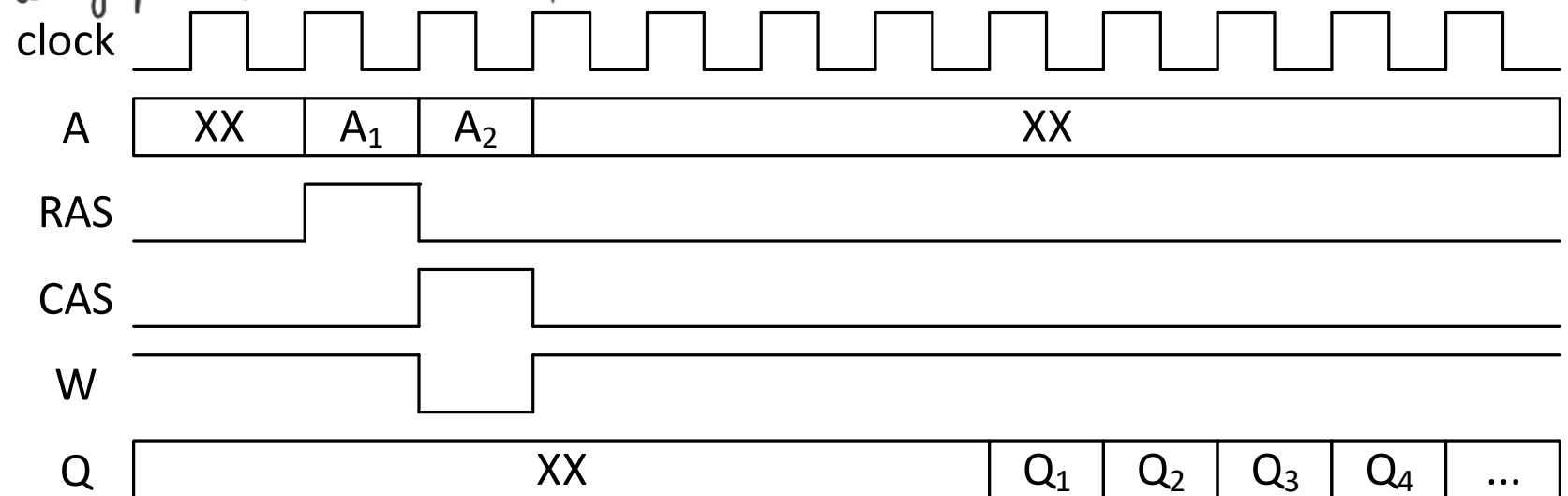
- Modern DRAMs are synchronous

- Control and data operations referenced to a common clock signal

- SDRAM** = Synchronous **DRAM**

- Burst mode** *accumulation latency for different clock cycles, then in sequence all the data that you need.*

- Initial latency followed by a flood of data



DDR

- **DDR = Double Data Rate**

- SDRAM in which control and data operations are performed on both edges of clock signal

- Rising edge
- Falling edge

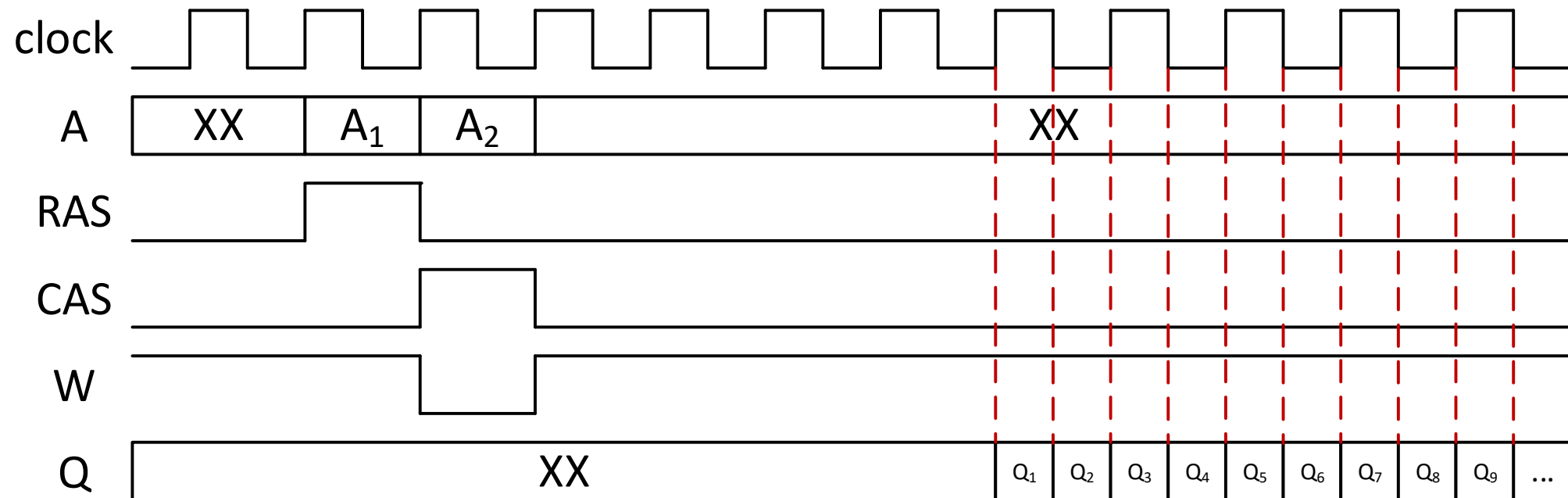
↳ Both edges used to perform operation.

- Data transfer rate is doubled!

- From here the name

- Standardized throughout the years

DDR



DDR

- Standards/generations

Generation	SDRAM	DDR	DDR2	DDR3	DDR4	DDR5
Year	1988	2000	2003	2007	2014	2021
Transfer rate (MT/s)	100 – 166	266 – 400	533 – 800	1066 – 1600	2133 – 5100	3200 – 6400
Data rate (GB/s)	0.8 – 1.3	2.1 – 2.3	4.2 – 4.6	8.5 – 14.9	17 – 25.6	38.4 – 51.2
Voltage (V_{CC})	3.3	2.5 – 2.6	1.8	1.35 – 1.5	1.2	1.1

Latest

megn transfers

down raises



Thank you for your attention

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